

EL465782143

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 08/886,388  
Priority Filing Date ..... July 1, 1997  
Inventor ..... Gurtej S. Sandhu et al.  
Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 2811  
Priority Examiner ..... Sara W. Crane  
Attorney's Docket No. .... MI22-1736  
Title: Method of Forming a Capacitor and a Capacitor Construction

**PRELIMINARY AMENDMENT**

To: Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.  
(Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 W. First Avenue, Suite 1300  
Spokane, WA 99201-3817

Sir:

This is a preliminary amendment accompanying a Request for Continuation Application for the above-entitled patent application. Prior to examining the application, please enter the following amendments.

**AMENDMENTS**

### **In the Specification**

At page 1, after the title, insert:

### **CROSS REFERENCE TO RELATED APPLICATION**

This patent application is a Continuation of U.S. Patent Application Serial No. 08/886,388 filed July 16, 1997, entitled "Method of Forming a Capacitor and a Capacitor Construction", naming Gurtej S. Sandhu and Pierre C. Fazan as inventors, which is a divisional application of United States Patent Application Serial No. 08/582,385, which was filed January 3, 1996, now U.S. Patent No. 6,218,237.

### **In the Claims**

Cancel claims 1-45 and add new claims 46-60 as shown below.

### **New Claims**

46. A pair of adjacent stacked capacitors fabricated on a semiconductor substrate, the adjacent stacked capacitors respectively each including:

a polycrystalline silicon lower plate, the lower plates having a minimum lateral spacing from one another that is less than a minimum photolithographic feature dimension with which the capacitors are fabricated; and

a plug extending below the plate and having a diameter less than the minimum photolithographic feature dimension.

47. The pair of capacitors of claim 46, wherein each plug comprises polysilicon and extends through the plate.

48. The capacitors of claim 46, wherein the lower plates are formed from conductive polysilicon.

49. The pair of capacitors of claim 46, wherein the pair of stacked capacitors are coated with a capacitor dielectric layer.

50. A pair of adjacent stacked capacitors fabricated on a semiconductor substrate using a process having a characteristic minimum lithographic feature dimension, the adjacent stacked capacitors respectively including a lower plate having a minimum lateral spacing from one another which is less than the minimum lithographic feature dimension, wherein each of the pair of capacitors comprises:

a plug having a diameter less than the minimum lithographic feature dimension; and

in cross-section, at least two laterally opposed fins interconnected with and projecting laterally from the plug.

51. The pair of capacitors of claim 50, wherein the plug and fins are formed from conductive polysilicon.

52. The pair of capacitors of claim 50, wherein the pair of stacked capacitors are coated with a capacitor dielectric layer.

53. A pair of adjacent stacked capacitors fabricated on a semiconductor substrate using a lithographic process having a characteristic minimum lithographic feature dimension, the adjacent stacked capacitors respectively including a lower plate having a minimum lateral spacing from one another which is less than the minimum lithographic feature dimension, each lower plate comprising a conductive plug having a diameter less than the minimum lithographic feature dimension, and, in cross-section, at least two laterally opposed fins interconnected with and projecting laterally from the plug.

54. The pair of capacitors of claim 53, wherein the plug includes a minimum width which is less than the minimum lithographic feature dimension.

55. The pair of capacitors of claim 53, wherein the plug and fins are formed from conductive polysilicon.

56. The pair of capacitors of claim 53, wherein the pair of stacked capacitors are coated with a capacitor dielectric layer.

57. A pair of adjacent stacked capacitors fabricated on a semiconductor substrate using a lithographic process having a characteristic minimum lithographic feature dimension, the adjacent stacked capacitors respectively including a finned lower plate having a minimum lateral spacing from one another which is less than the minimum lithographic feature dimension, wherein each finned lower plate comprises:

a conductive plug; and

in cross-section, at least two laterally opposed fins interconnected with and projecting laterally from the plug, the plug having a minimum width which is less than the minimum lithographic feature dimension.

58. The pair of capacitors of claim 58, wherein the plug and lower plates are formed from conductive polysilicon.

59. The pair of capacitors of claim 58, wherein the plug and fins are formed from conductive polysilicon.

60. The pair of capacitors of claim 58, wherein the pair of stacked capacitors are coated with a capacitor dielectric layer.

**REMARKS**

Claims 1-45 have been canceled and new claims 46-60 have been added.

New claims 46-60 are supported at least by p. 4, line 5 through p. 13, line 3 of the application as originally filed. No new matter is added by new claims 46-60.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page(s) are captioned "**Version with markings to show changes made.**"

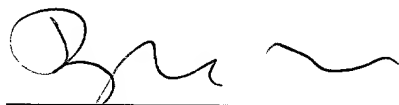
This application is believed to be in condition for allowance and action to that end is requested. The Examiner is requested to telephone the undersigned in the event that the next office action is one other than a Notice of Allowance. The undersigned is available during normal business hours (Pacific Time Zone).

Respectfully submitted,

Dated:

June 6, 2001

By:



Frederick M. Fliegel, Ph.D.  
Reg. No. 36,138

**Version with markings to show changes made.**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 2811  
Priority Examiner ..... Sara W. Crane  
Attorney's Docket No. .... MI22-1736  
Title: Method of Forming a Capacitor and a Capacitor Construction

**37 CFR §1.121(b)(1)(iii) AND 37 CFR §1.121(c)(1)(ii)**  
**FILING REQUIREMENTS TO ACCOMPANY PRELIMINARY AMENDMENT**

Deletions are bracketed, additions are underlined.

**In the Specification**

At page 1, after the title, the following was inserted:

**CROSS REFERENCE TO RELATED APPLICATION**

This patent application is a Continuation of U.S. Patent Application  
Serial No. 08/886,388 filed July 16, 1997, entitled "Method of Forming a  
Capacitor and a Capacitor Construction", naming Gurtej S. Sandhu and Pierre  
C. Fazan as inventors, which is a divisional application of United States  
Patent Application Serial No. 08/582,385, which was filed January 3, 1996,  
now U.S. Patent No. 6,218,237.

**END OF DOCUMENT**

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TITLE: Method of Forming a Capacitor and a Capacitor Construction

Assistant Commissioner for Patents  
Washington, D. C. 20231  
Attention: Official Draftsman

**SUBSTITUTE DRAWING REQUEST**

Enclosed are Red-line drawings of Figs. 1-22 along with corrected substitute formal drawings. Please enter the enclosed substitute formal drawings in the above-referenced application in place of drawings originally filed. The content of the drawings are identical to those now on file in this application.

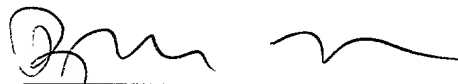
Acknowledgment of receipt of the formal drawings and their acceptance into the file is requested.

Respectfully submitted,

Date:

June 6, 2001

By:



Frederick M. Fliegel, Ph.D.

Reg. No.: 36,138

WELLS, ST. JOHN, ROBERTS,

GREGORY & MATKIN P.S.

601 W. First Avenue, Suite 1300

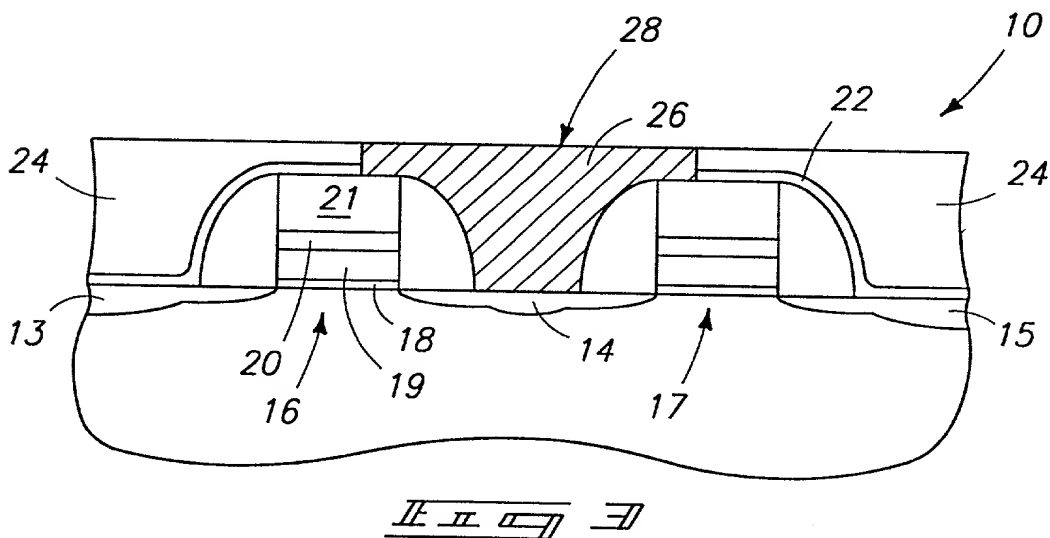
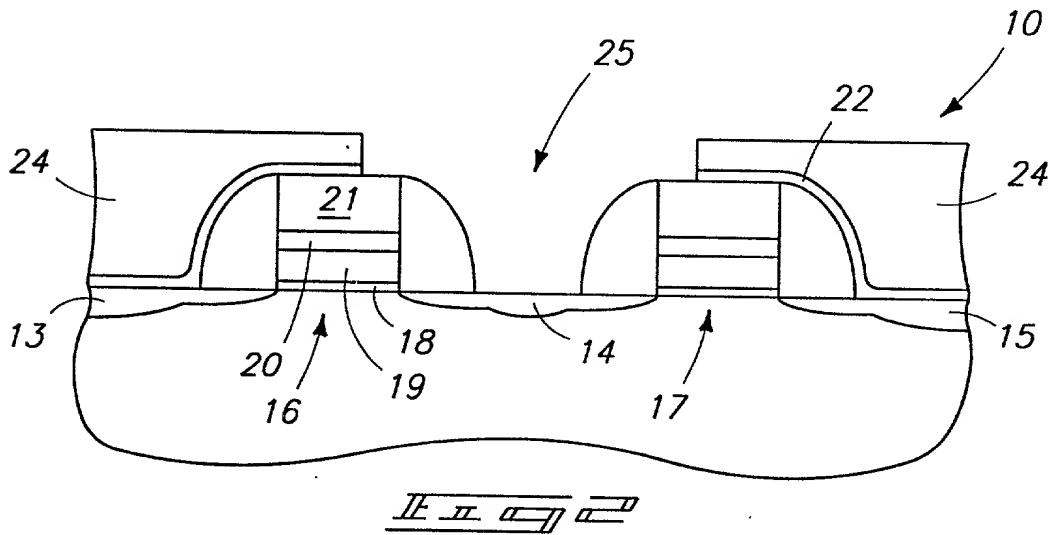
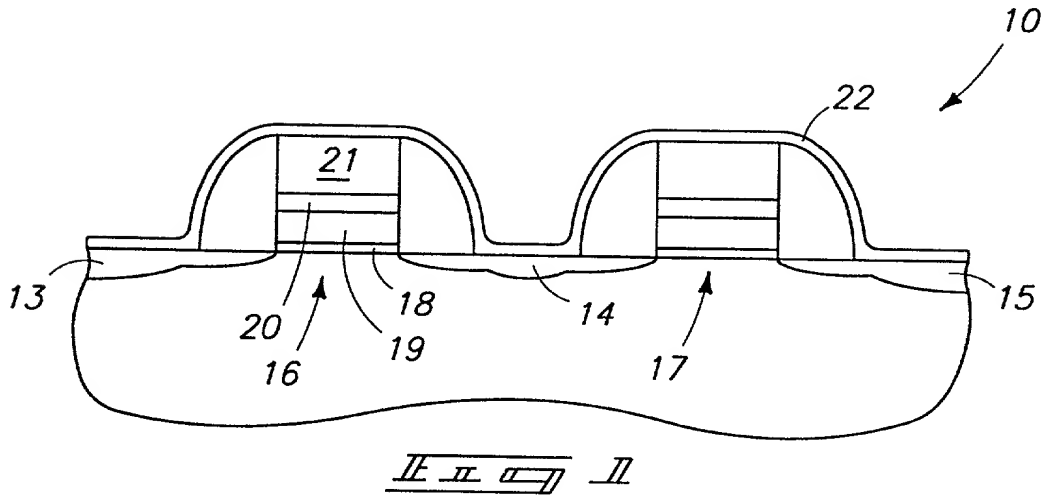
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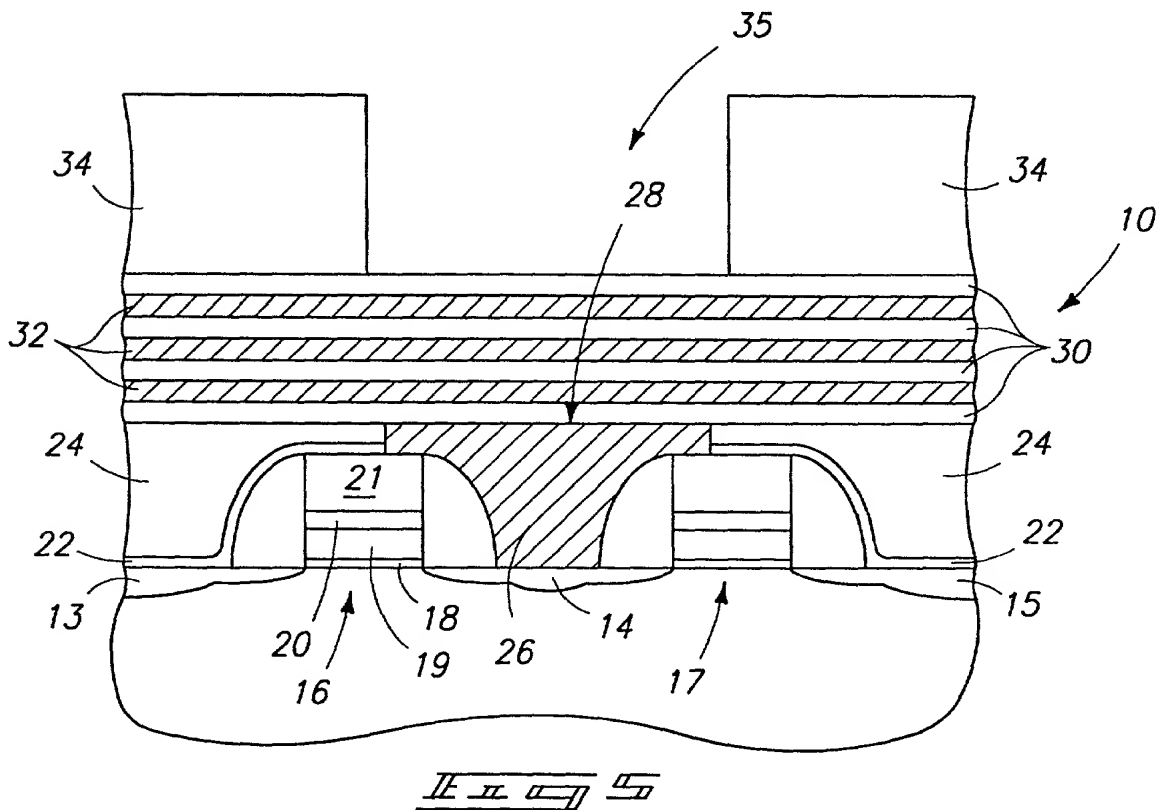
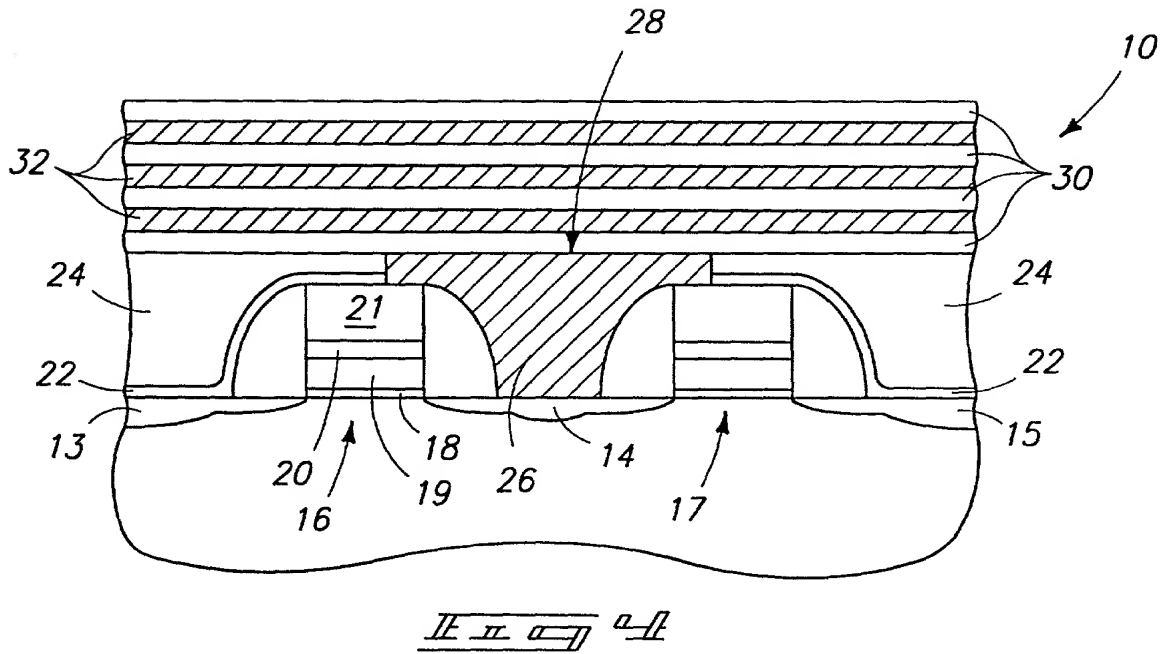
Enclosures: 12 sheets of Red-line Drawings, Figs. 1-22 and 12 Sheets of Formal Drawings, Figs. 1-22.



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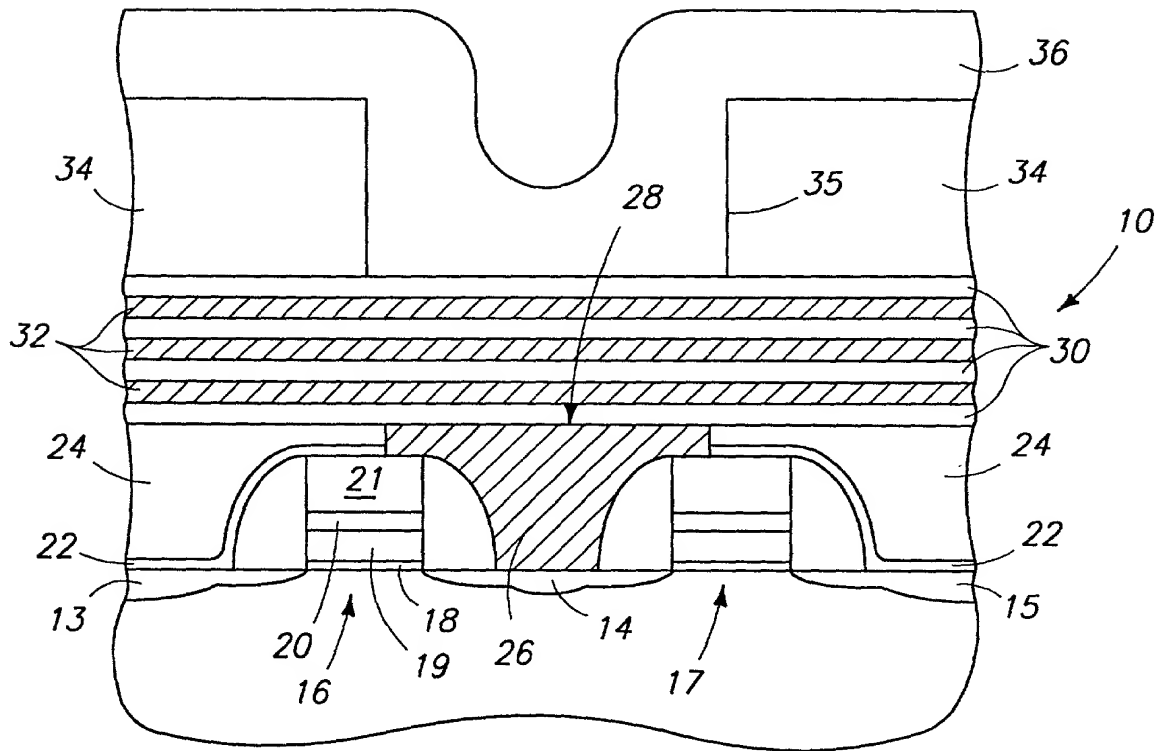


FIG. 1

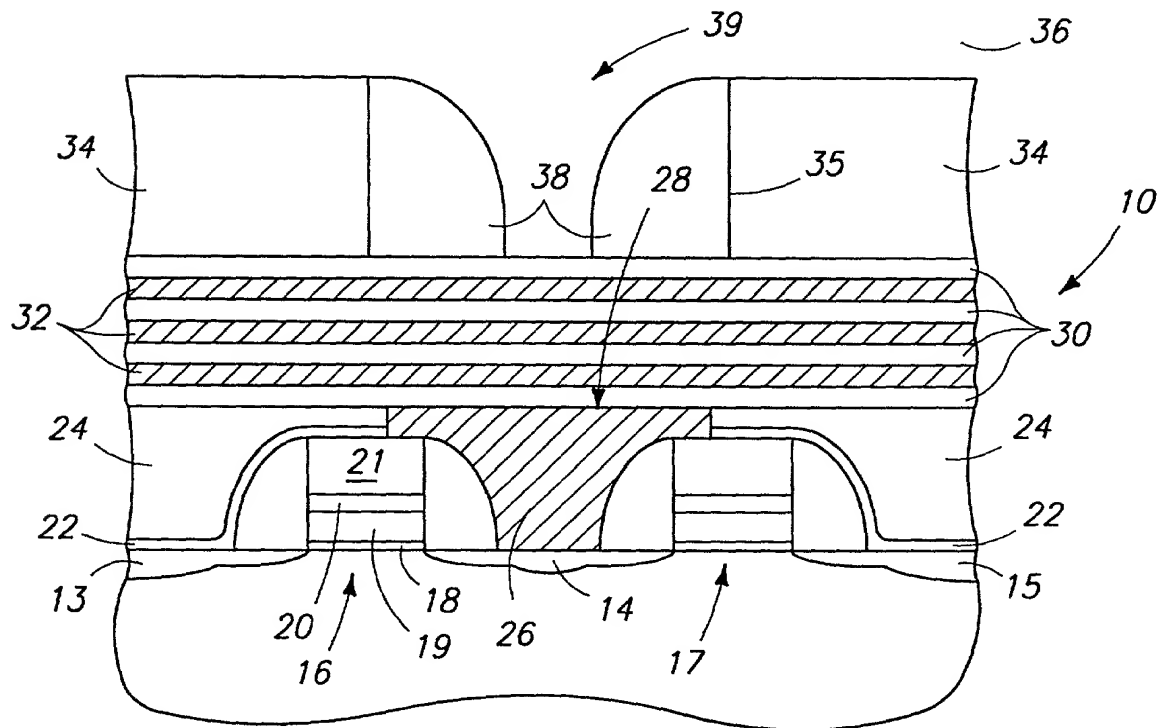
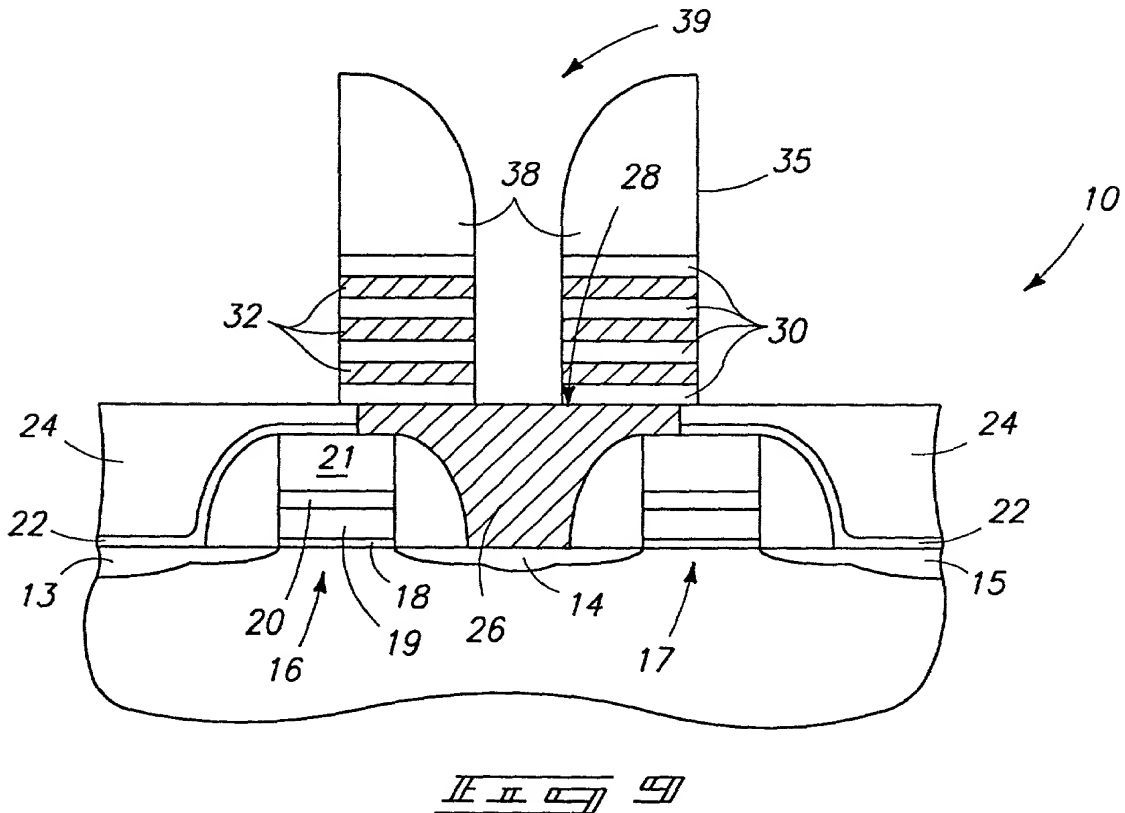
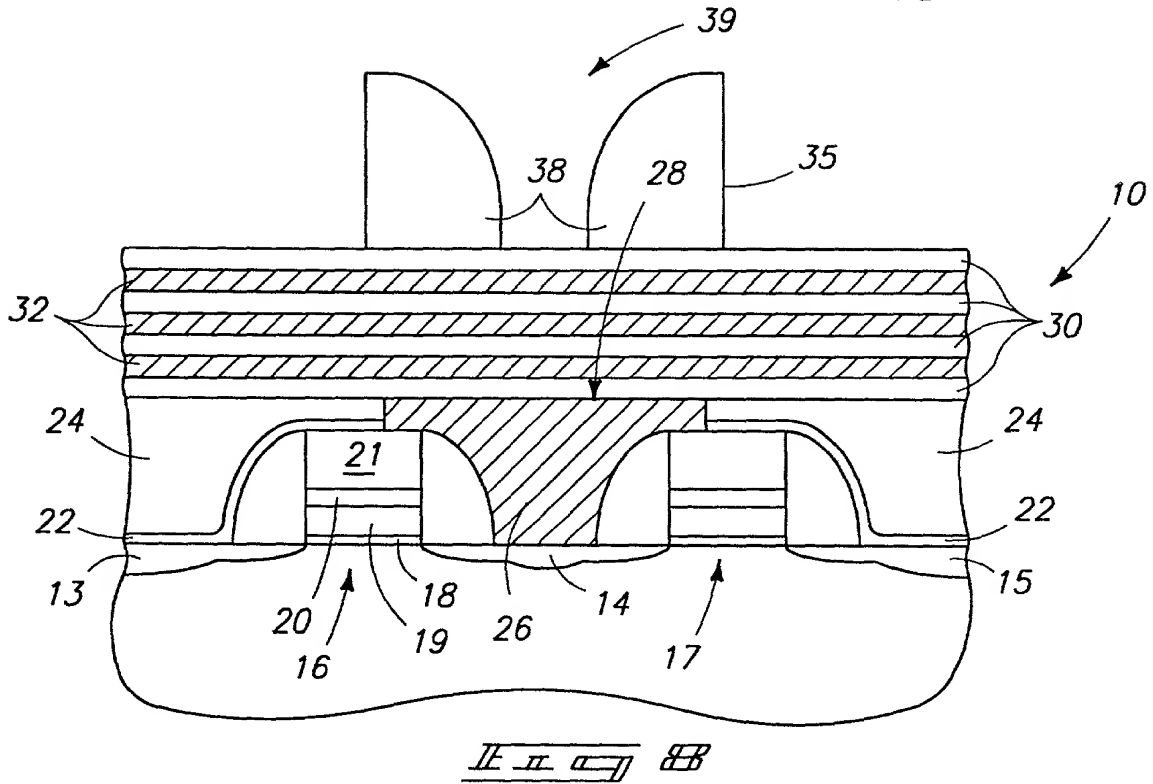


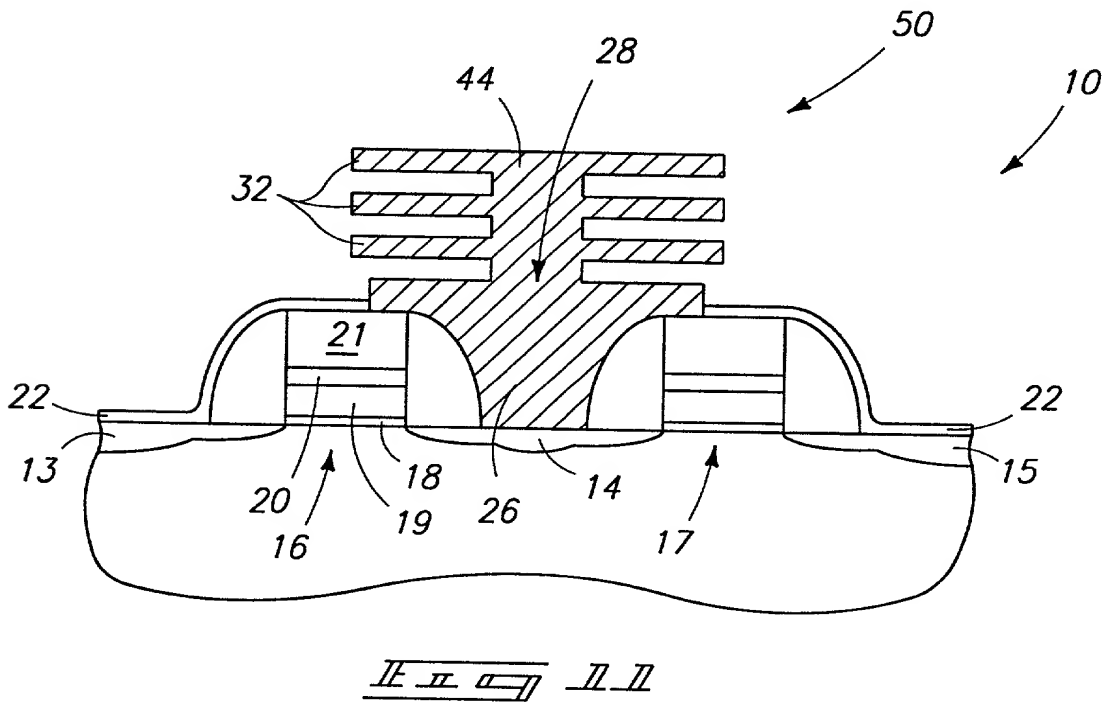
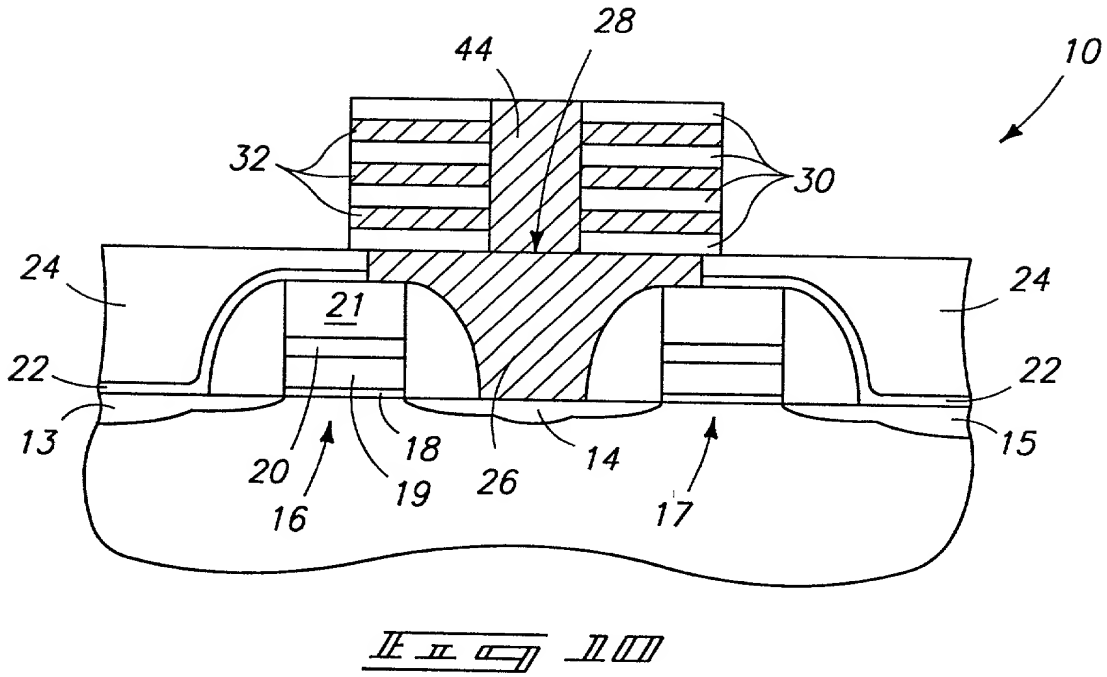
FIG. 2

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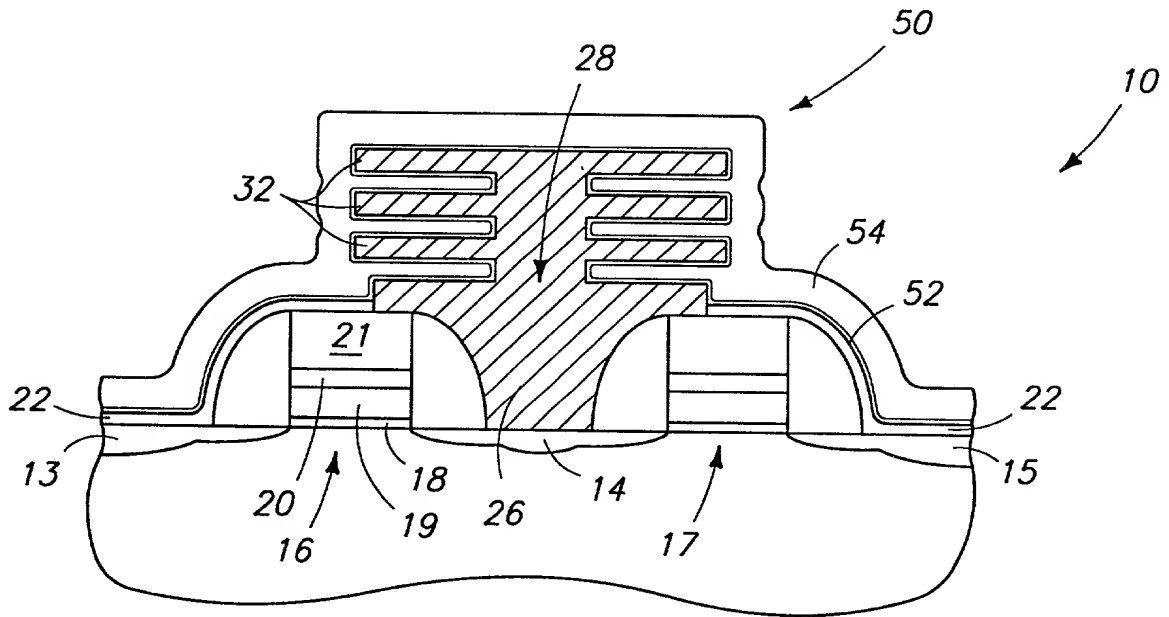


FIG. 1

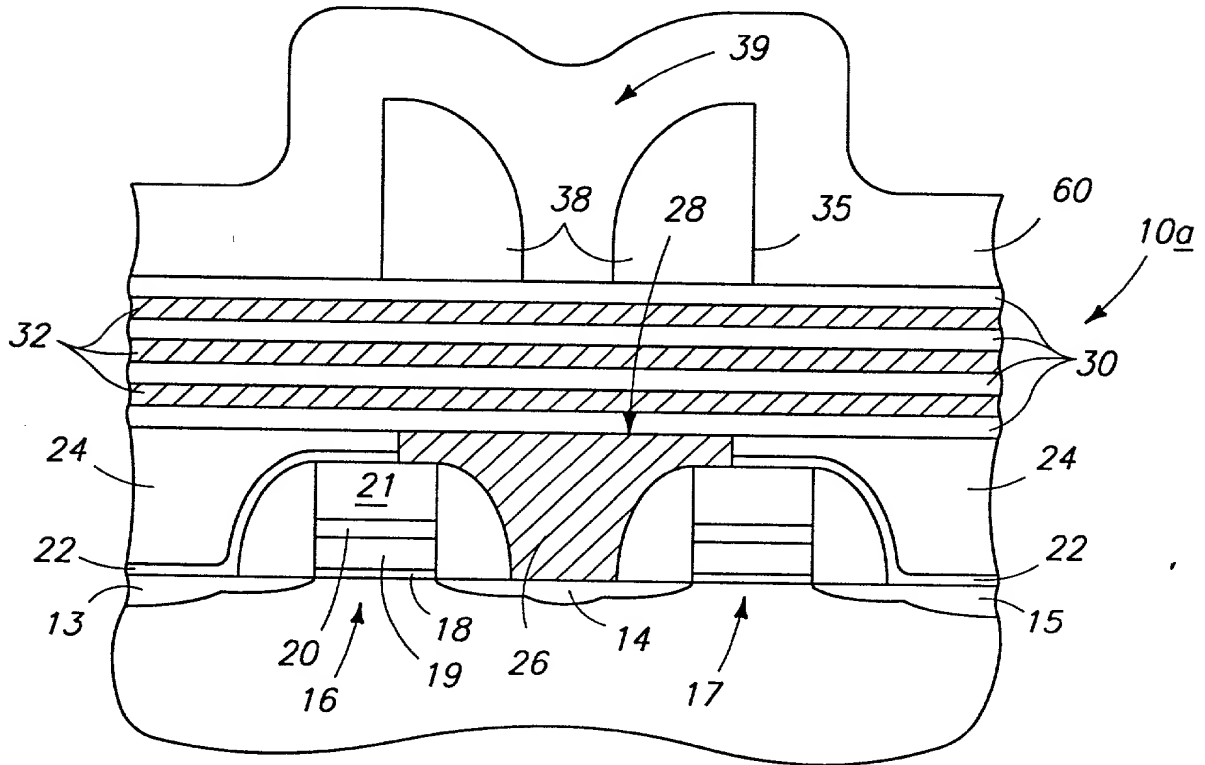
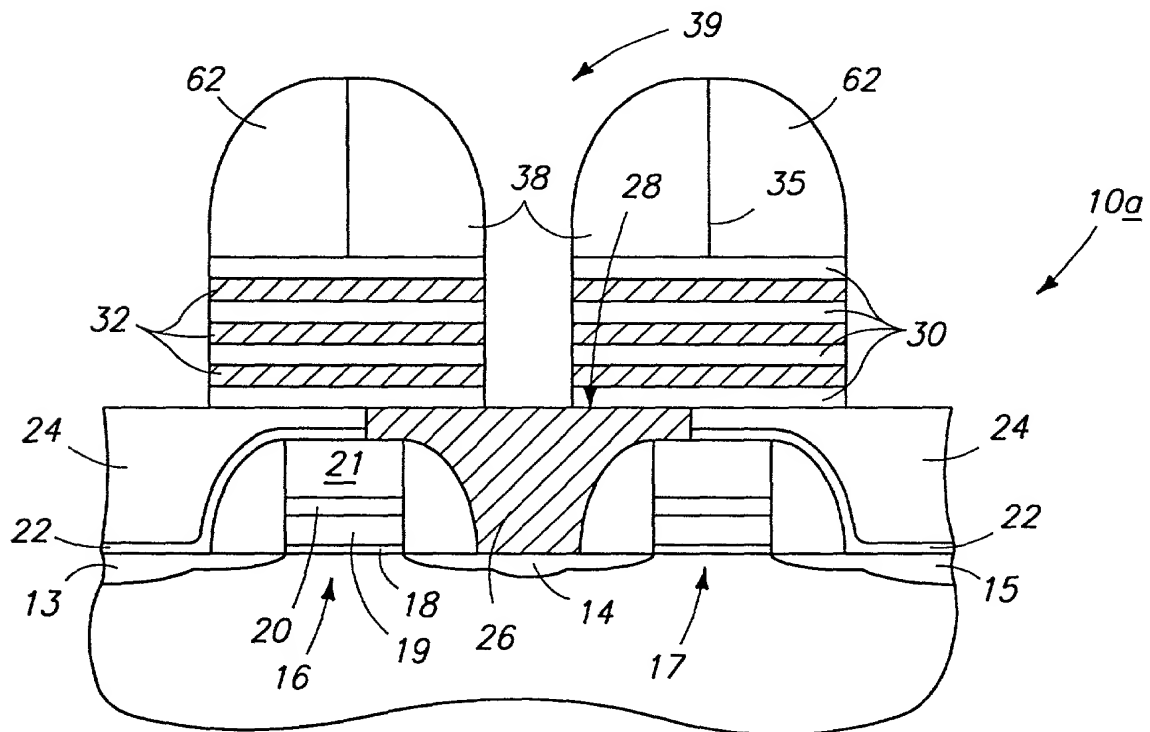


FIG. 2

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A cross-sectional view of a semiconductor device 10a. The device features a substrate 13 with a base layer 15. A central region 14 is filled with a material having diagonal hatching. On either side of this central region are two identical structures. Each structure includes a lower portion 16, a middle portion 18, and an upper portion 20. The middle portion 18 is further divided into sub-regions 19 and 21. The upper portion 20 is topped by a layer 22. The entire structure is surrounded by a layer 24. Above the central region 14, there is a layer 30 with diagonal hatching, and above that, a layer 32 with diagonal hatching. The top surface of the device is covered by a layer 38, which is divided into two main sections 35 and 39. Each section is topped by a dome-shaped structure 62.

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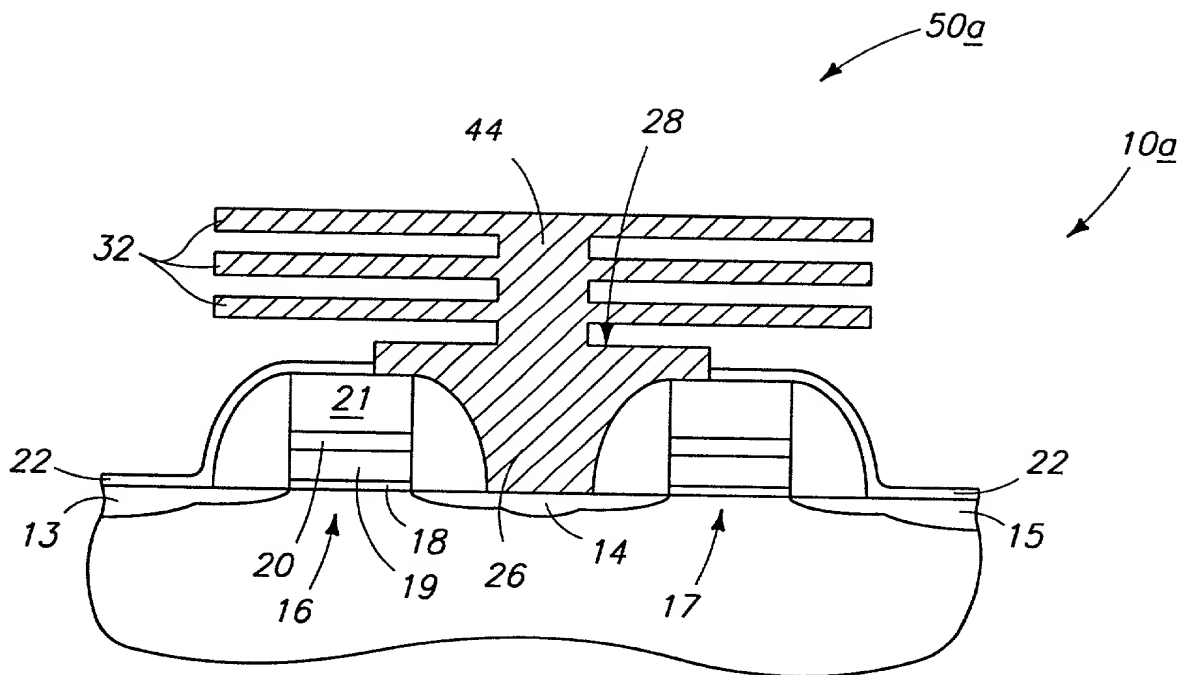

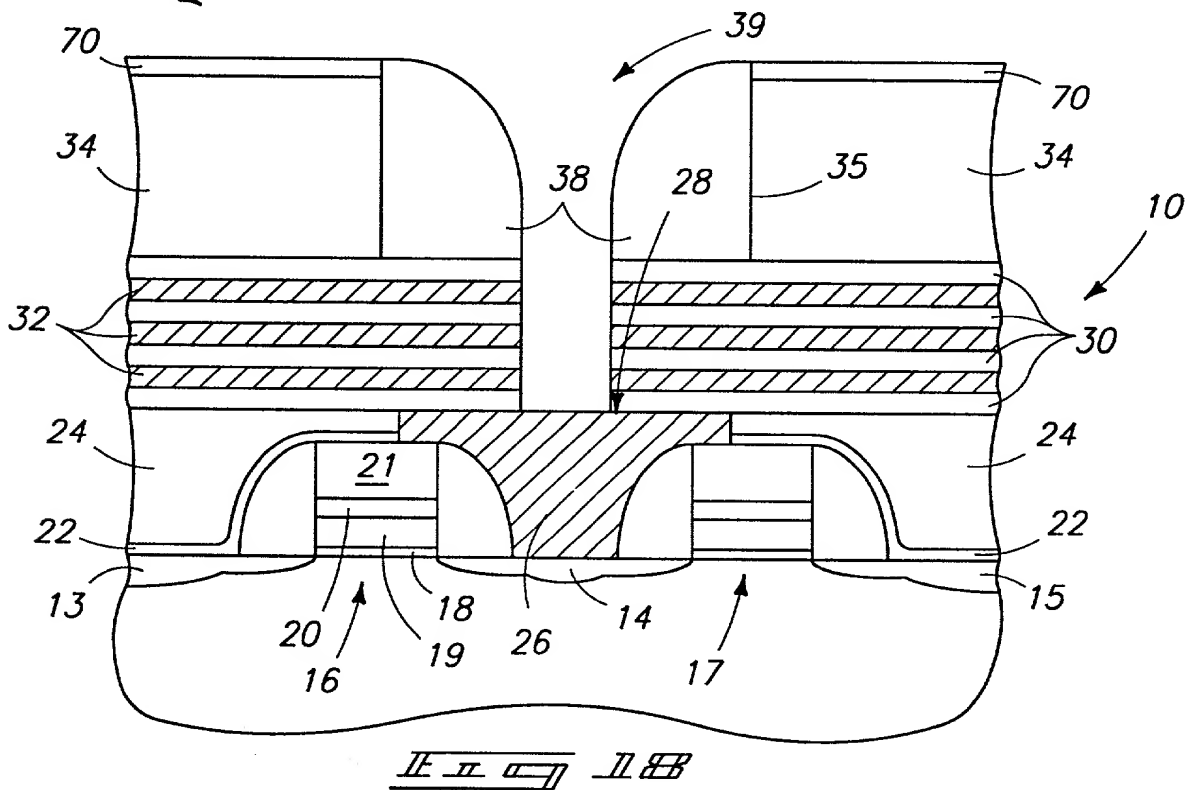
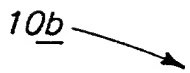


FIG. 1

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10b 



10b

44b

70

34

38

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14

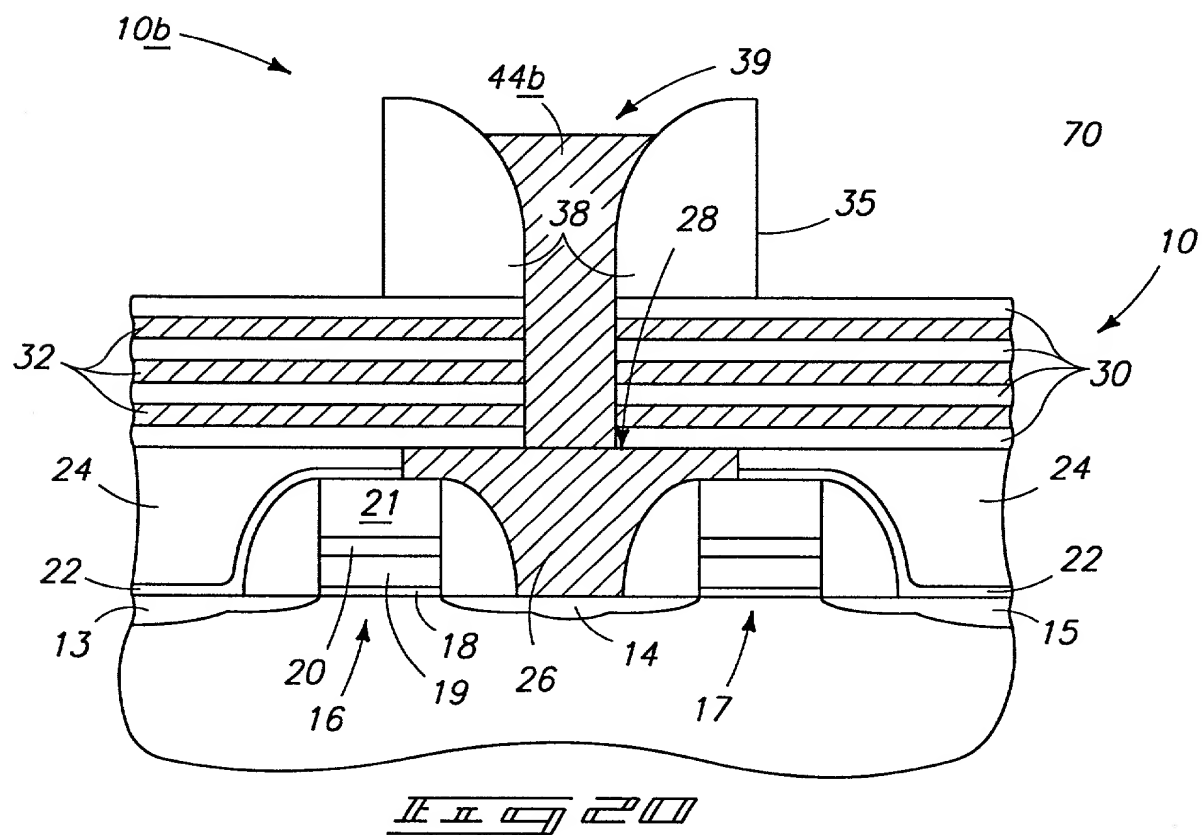
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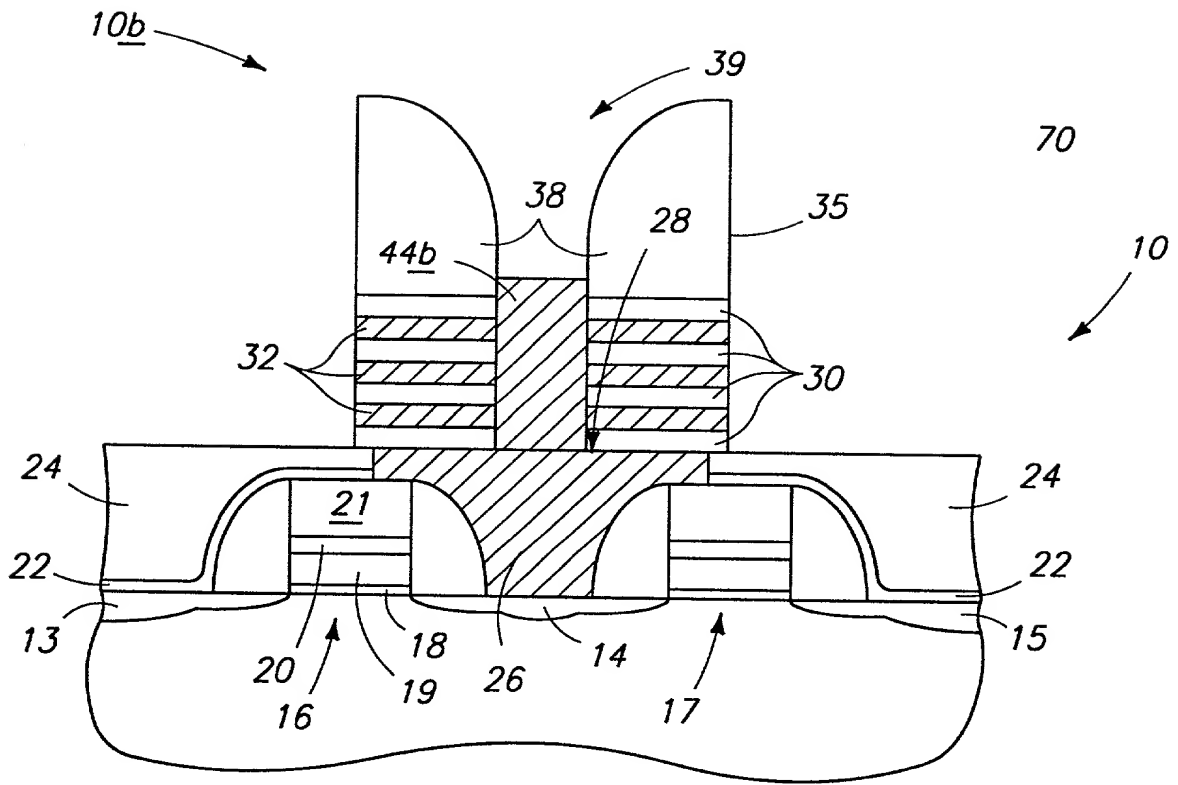


FIG. 11

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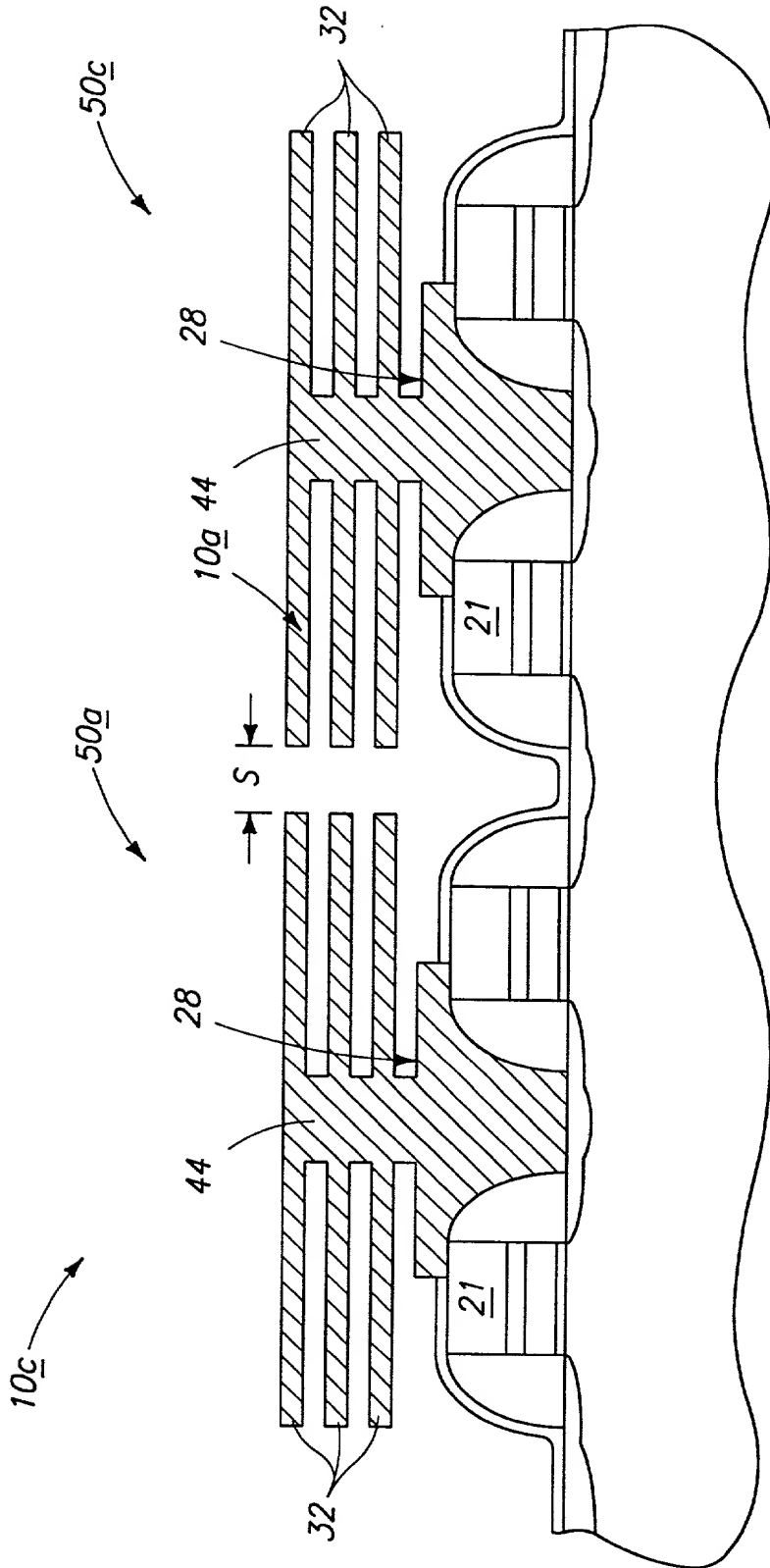
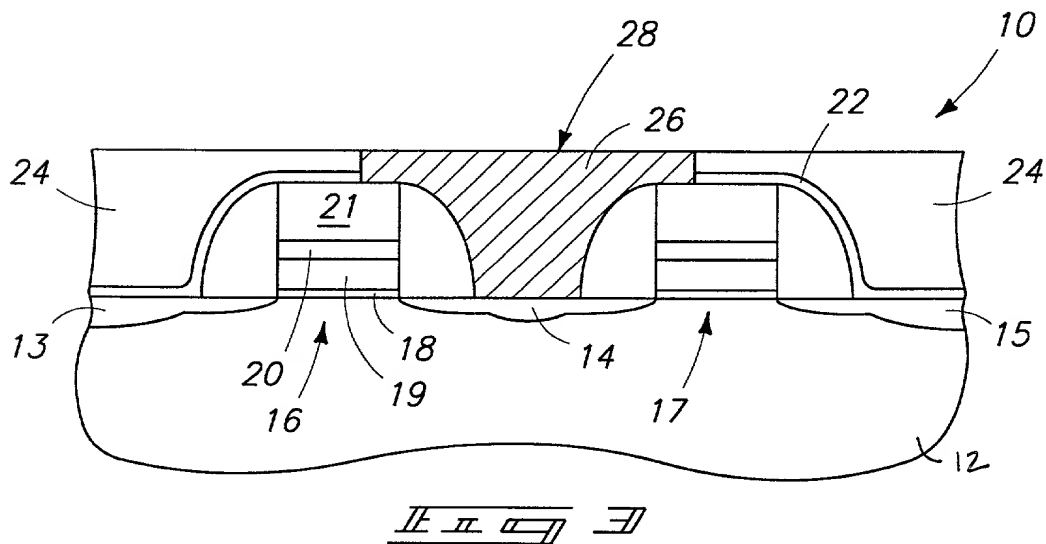
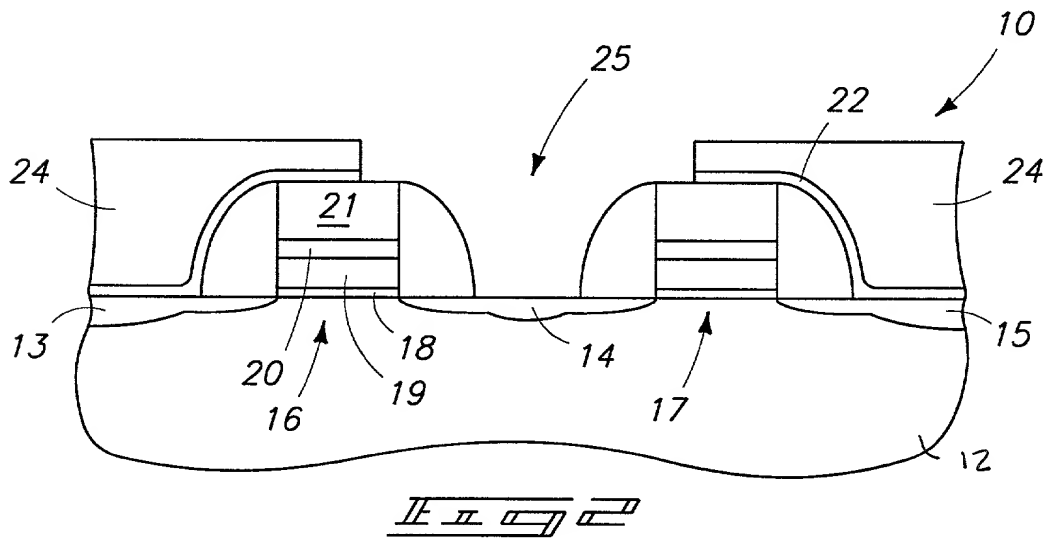
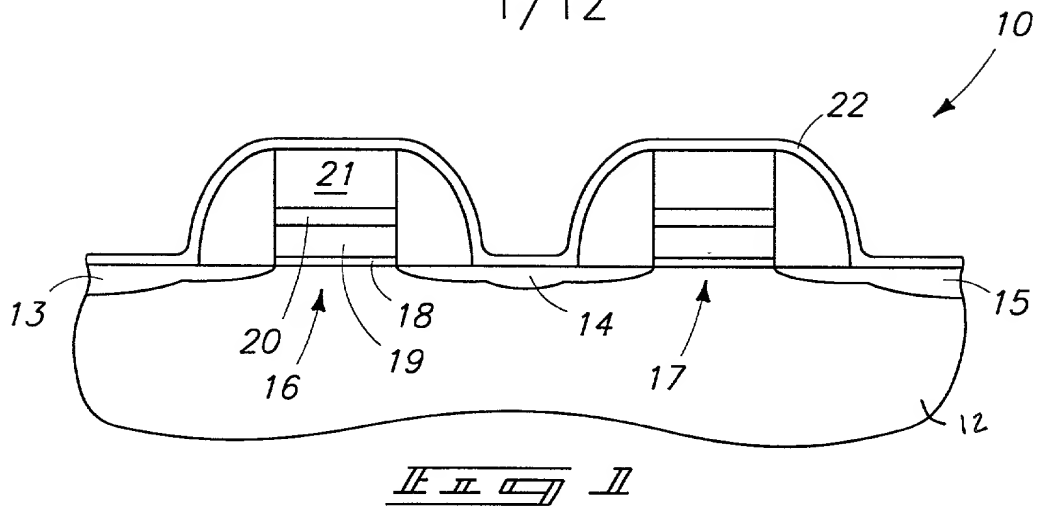
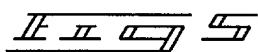
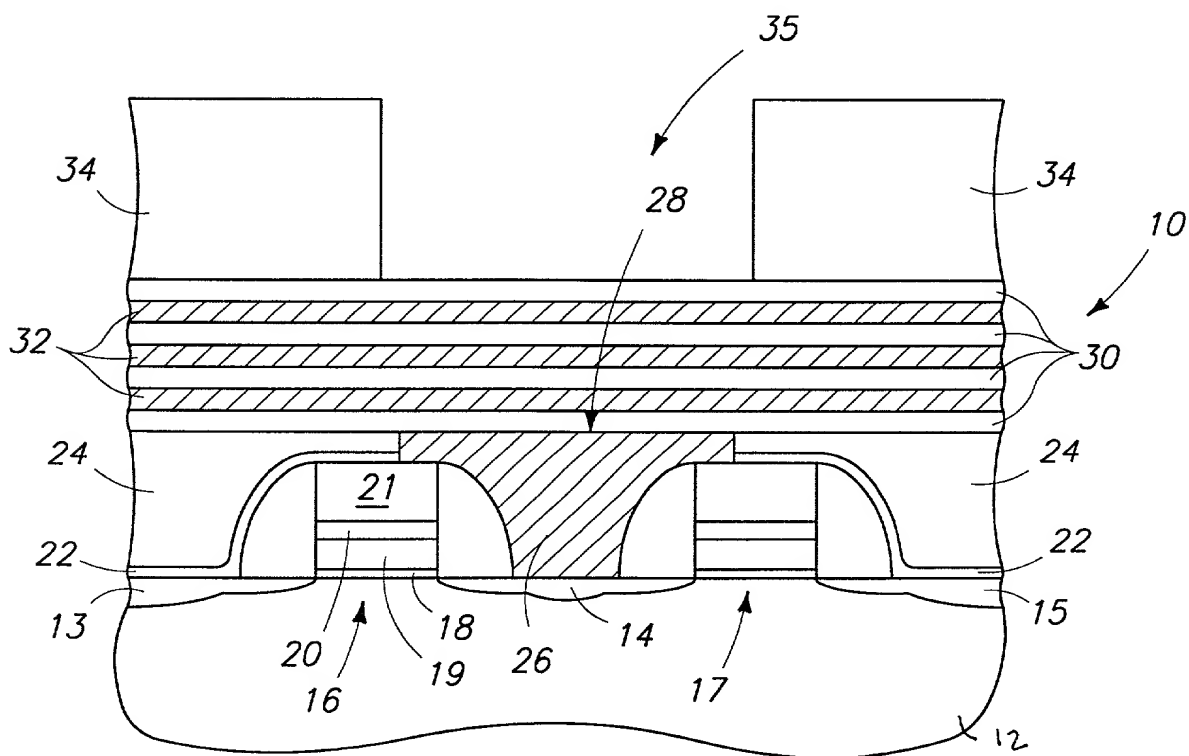
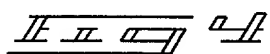
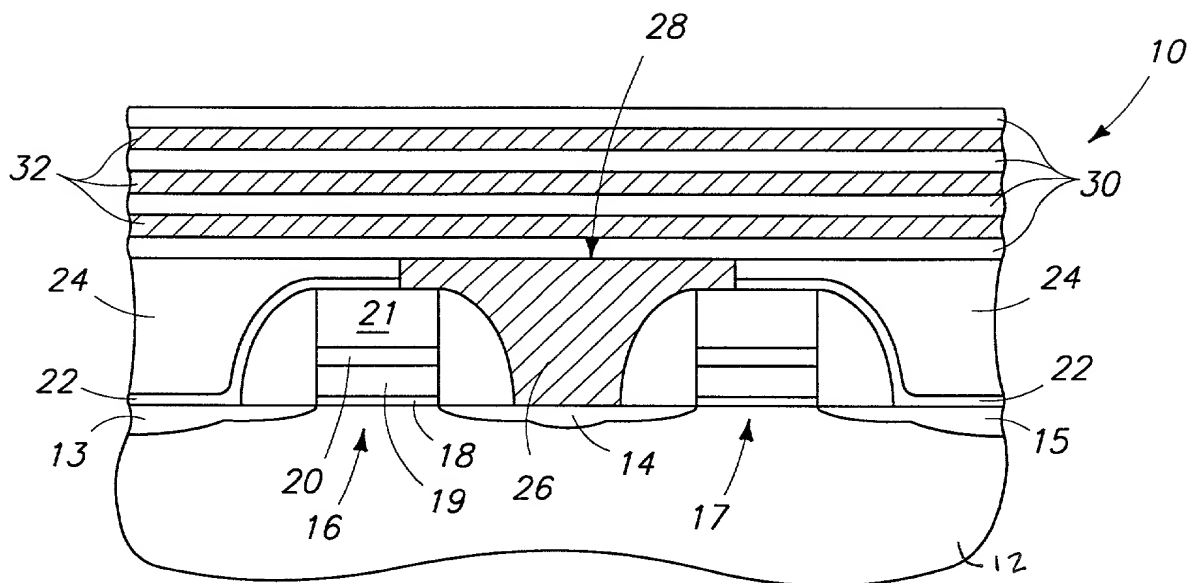


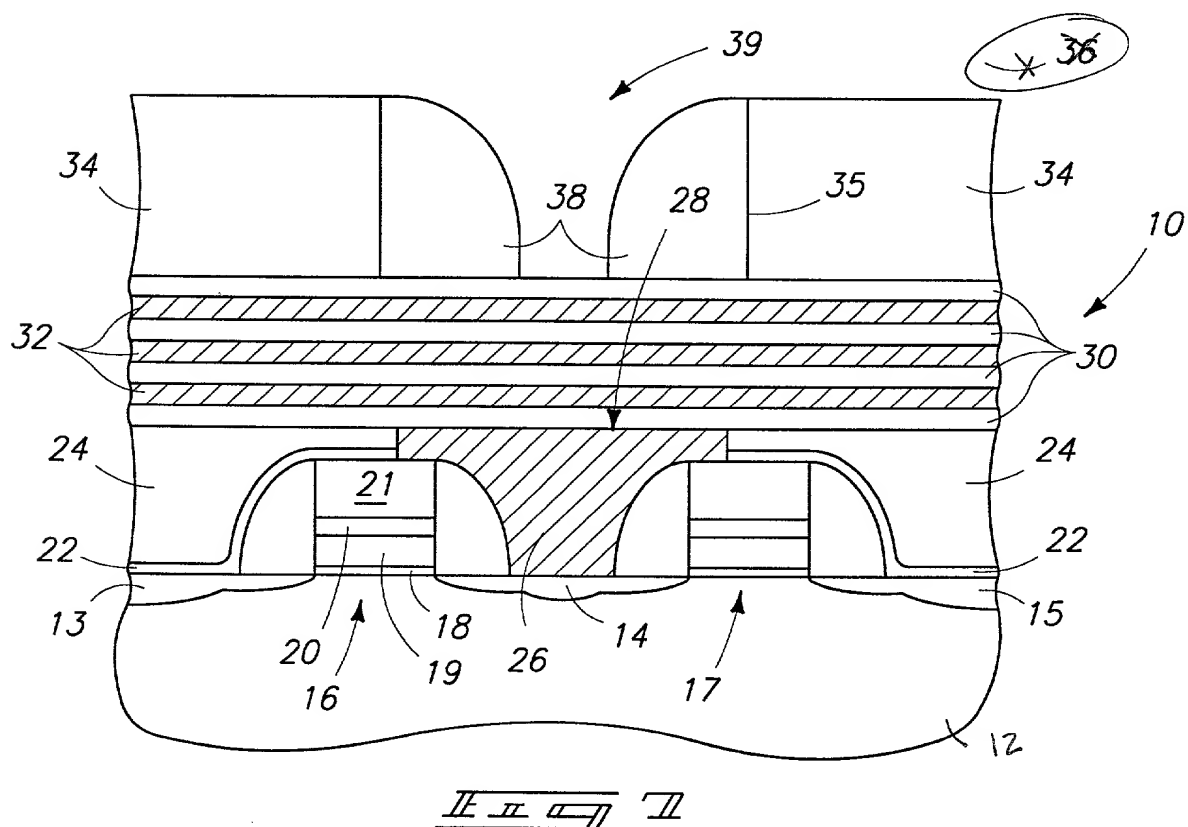
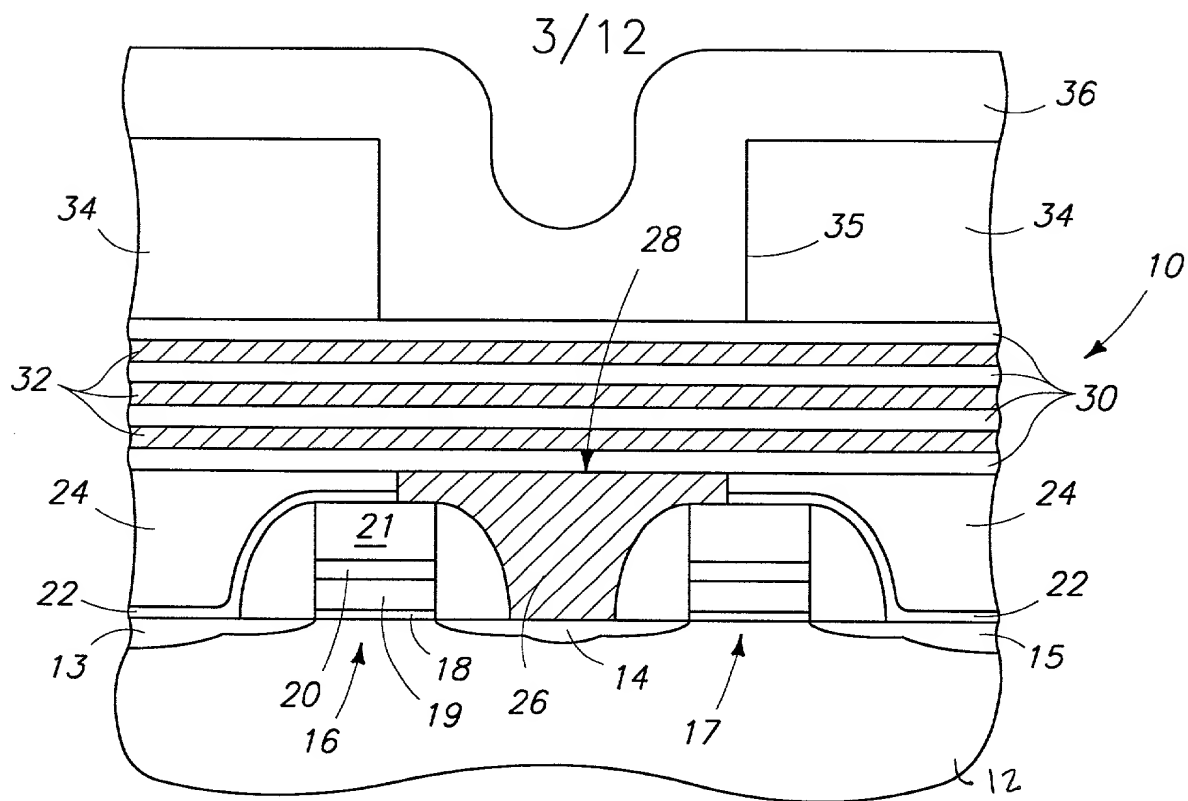
FIG. 2

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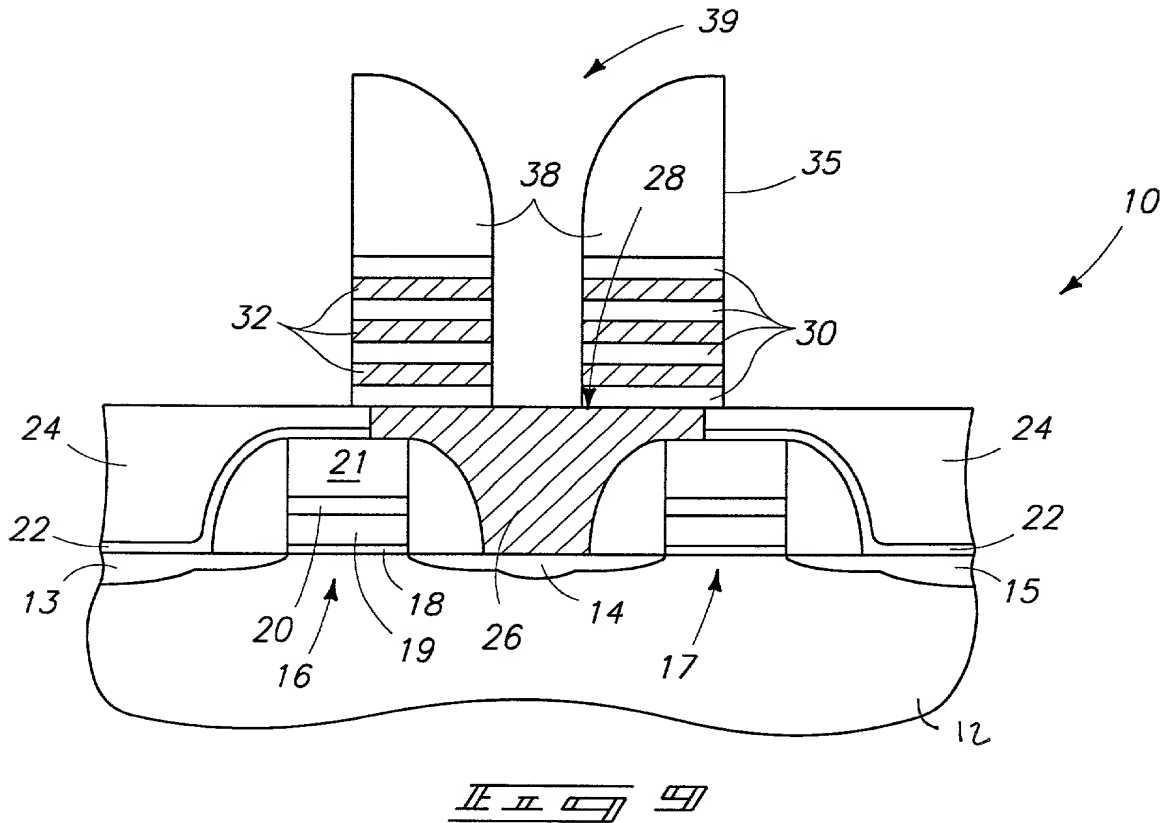
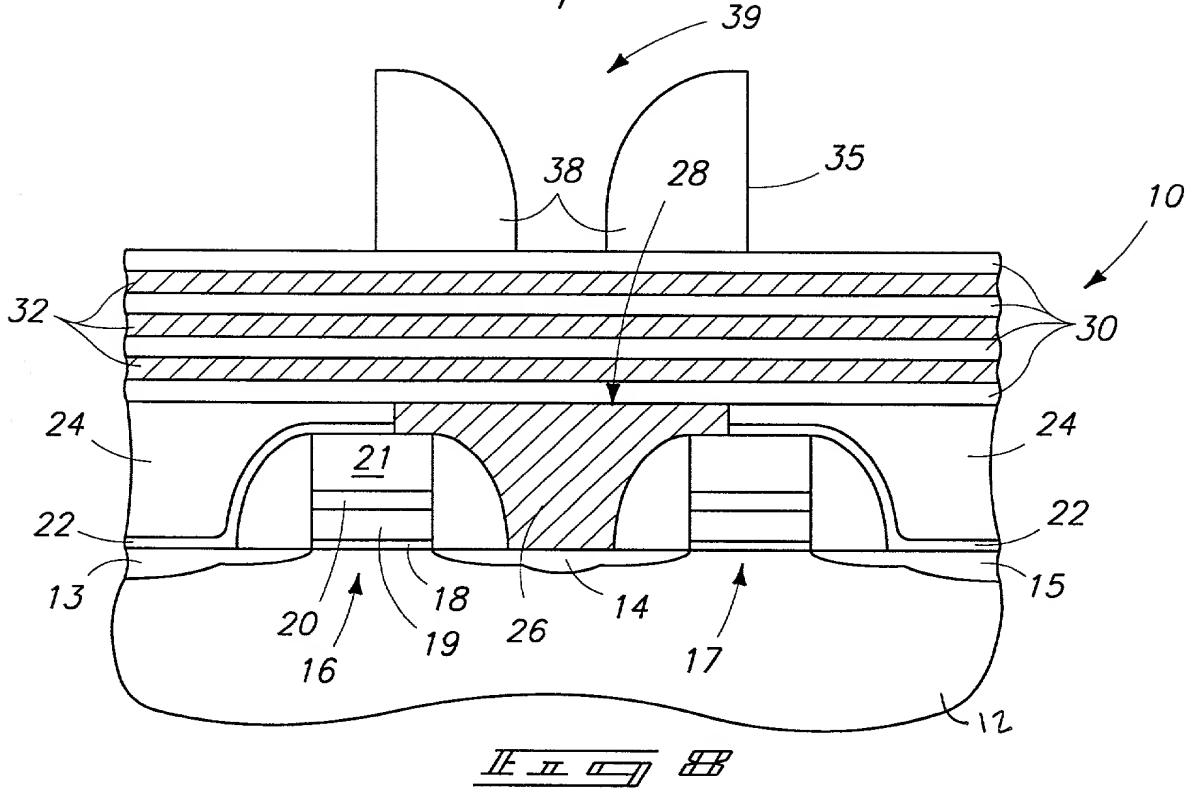


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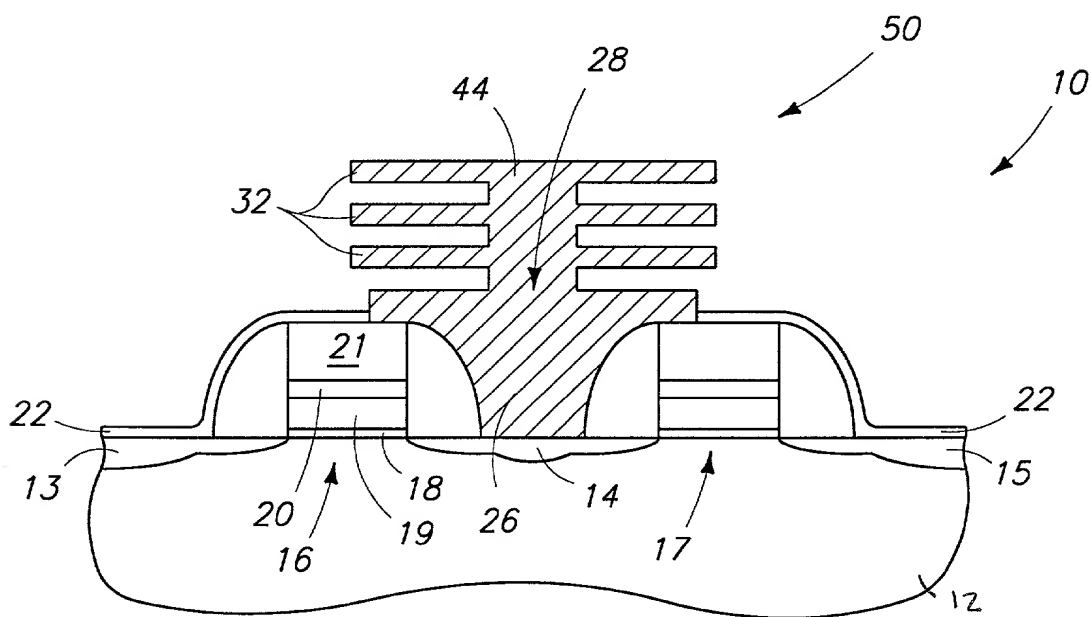
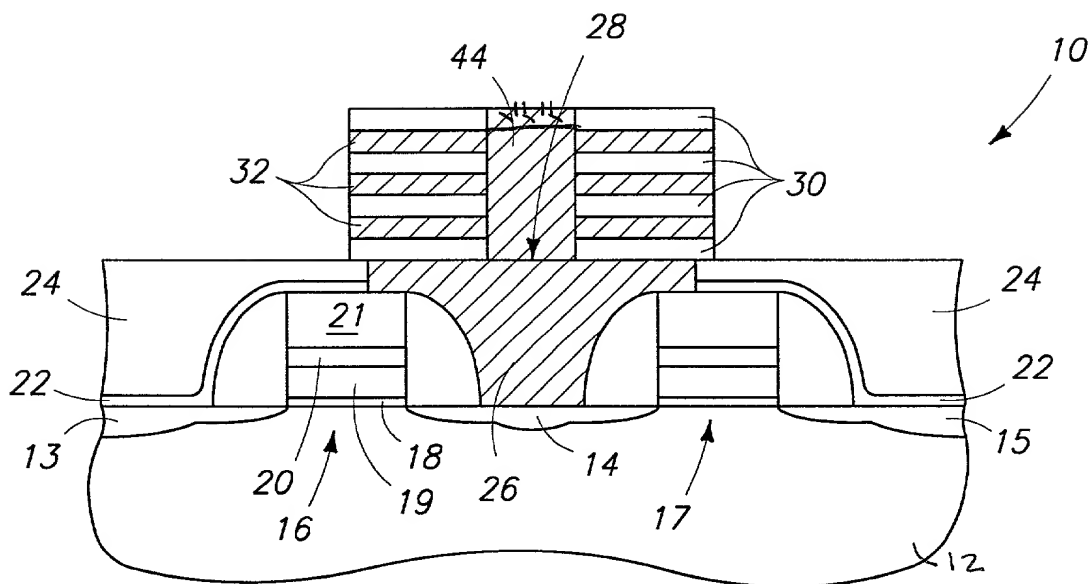


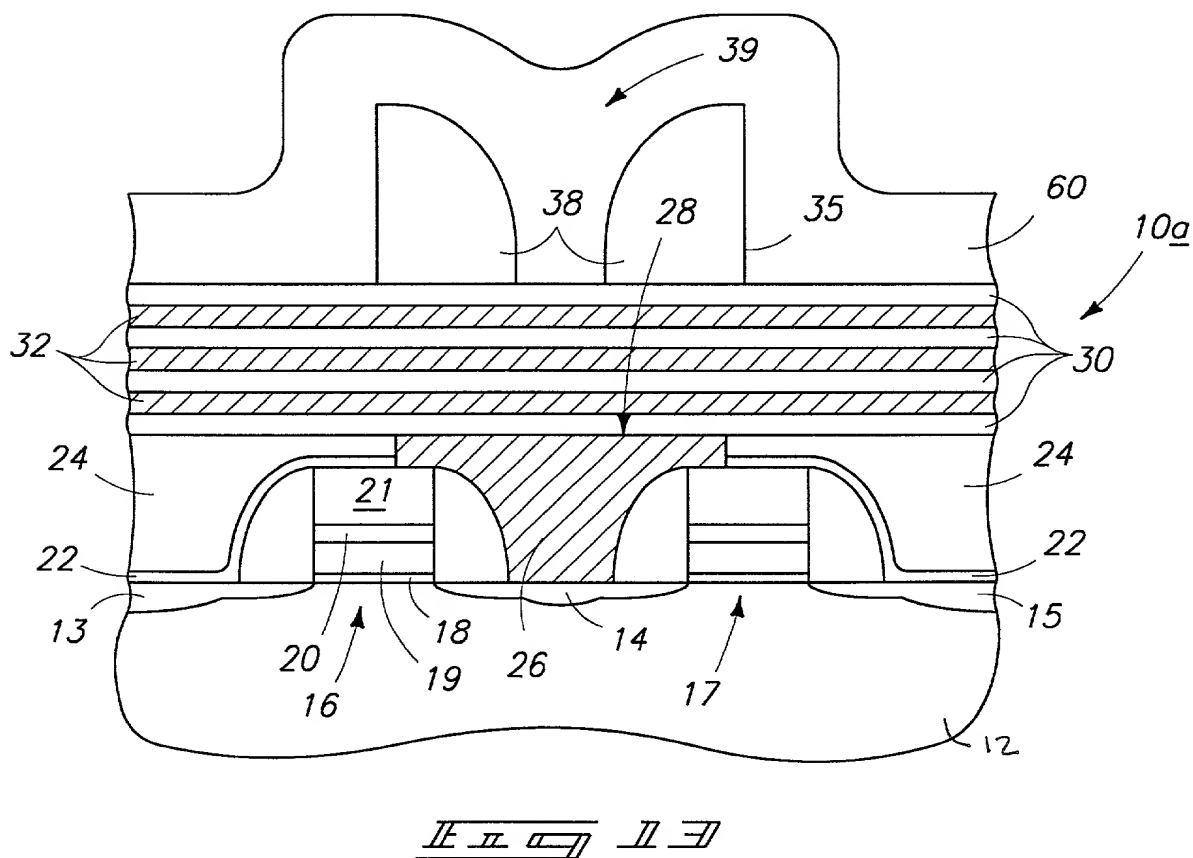
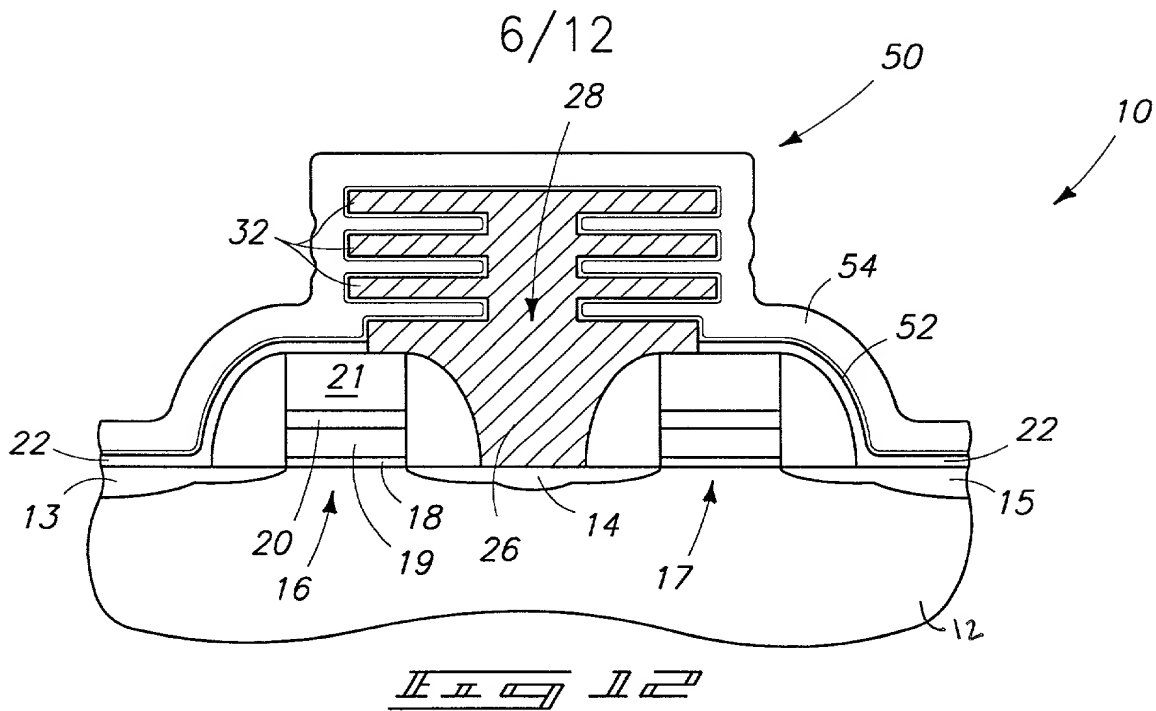
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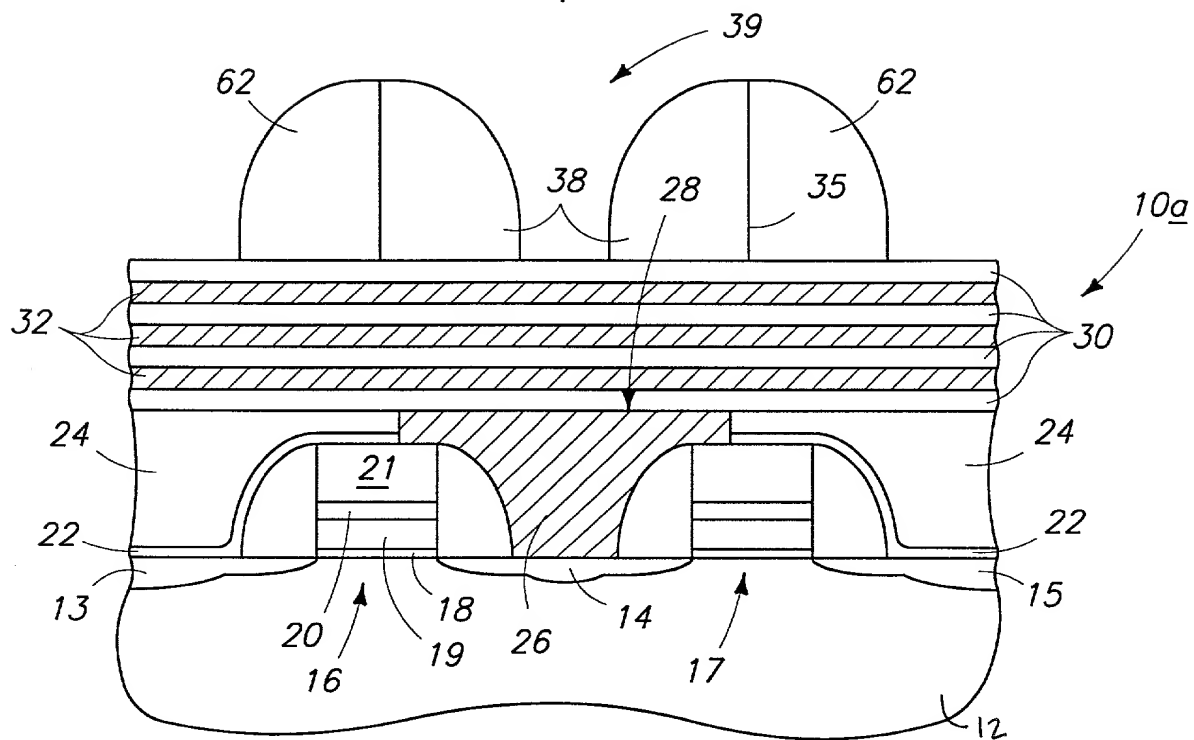


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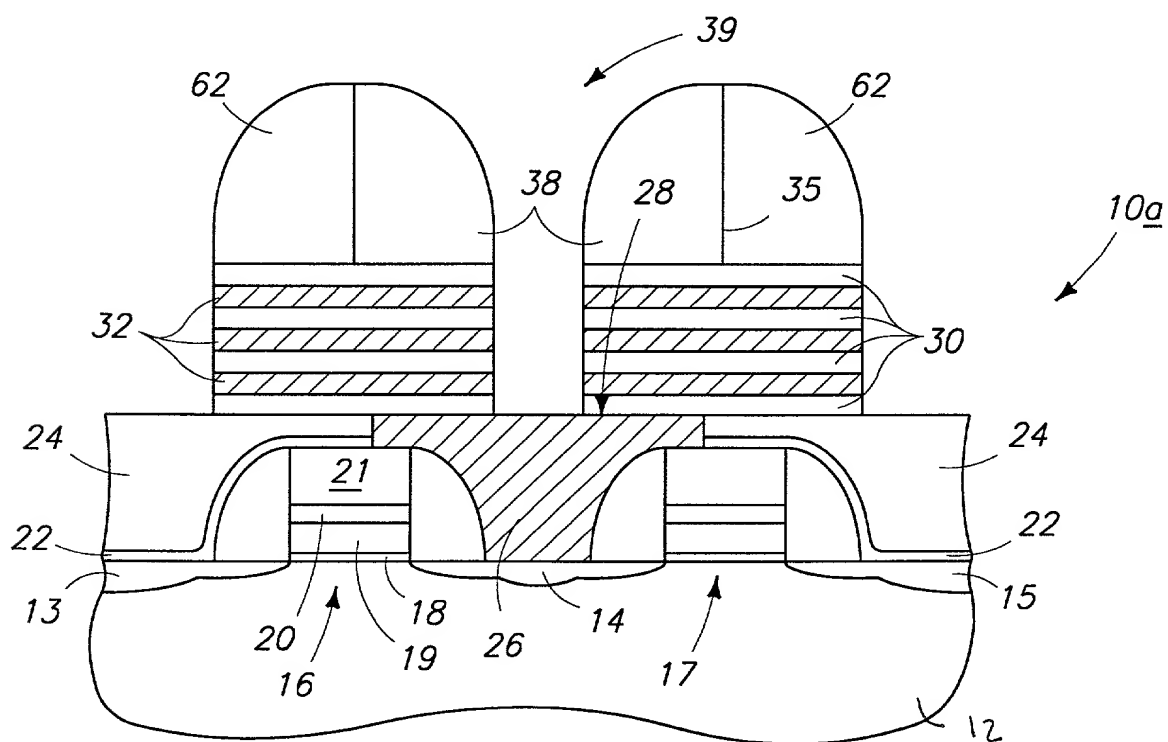




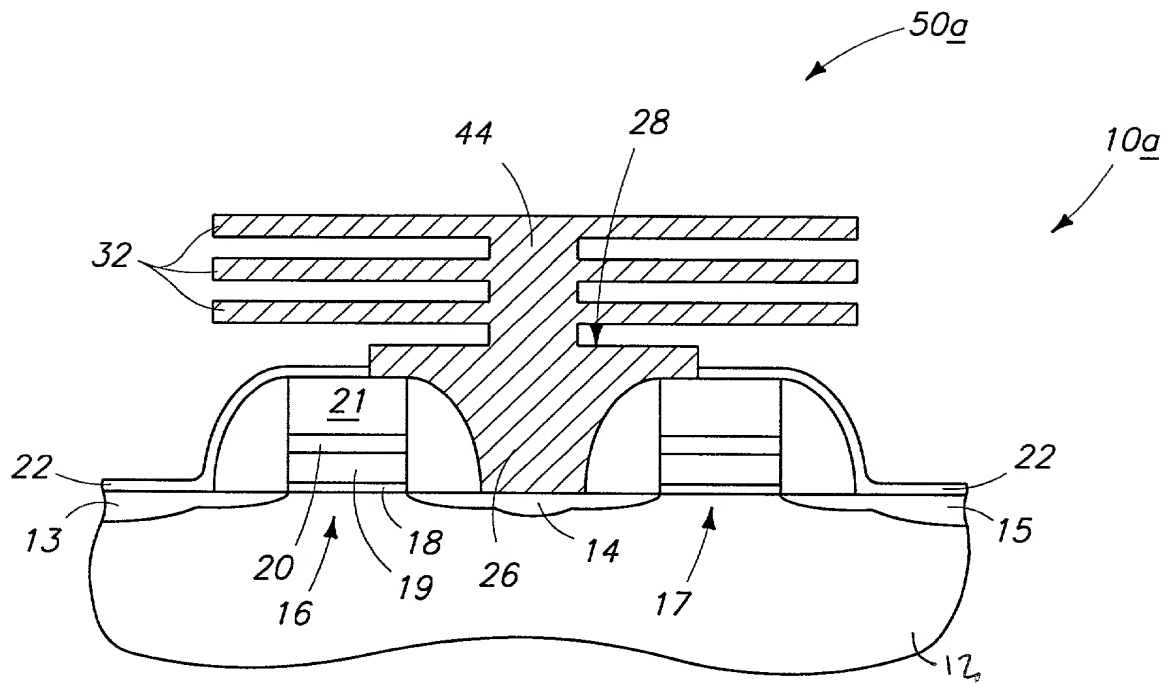
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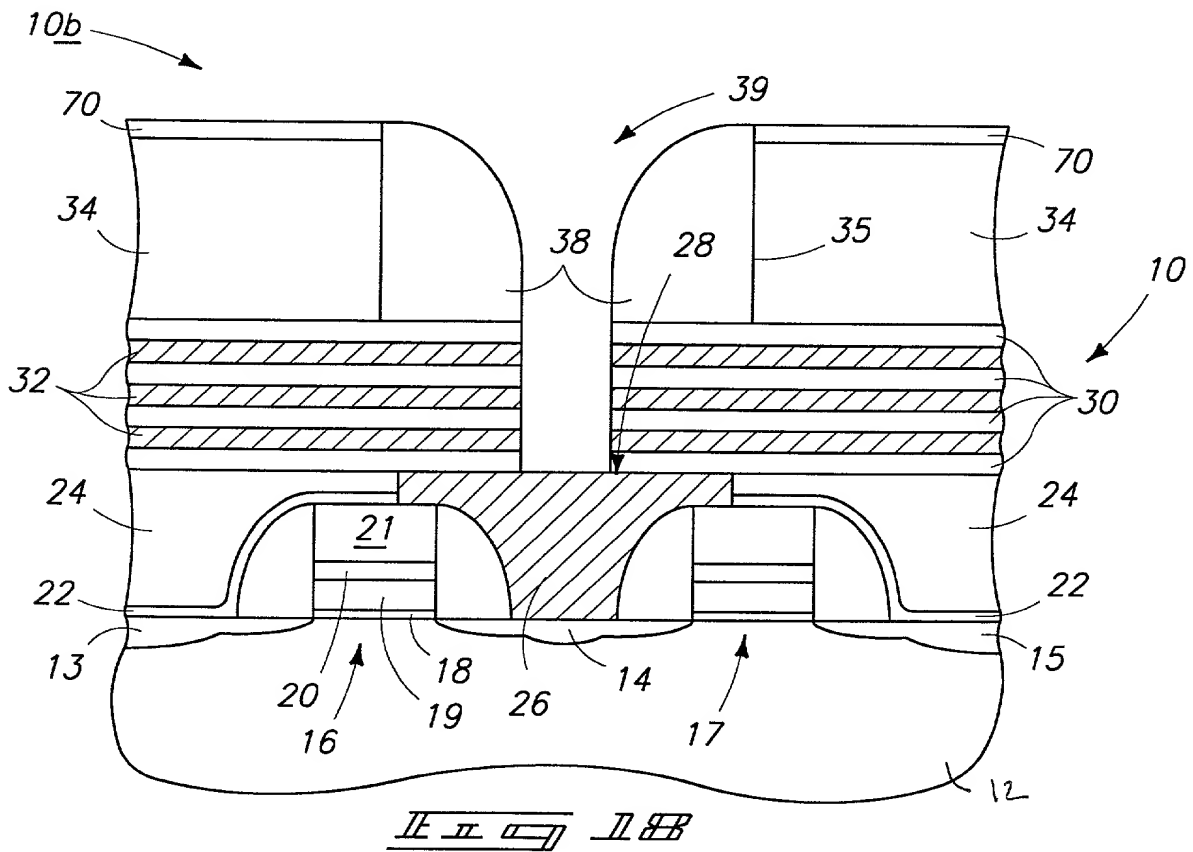
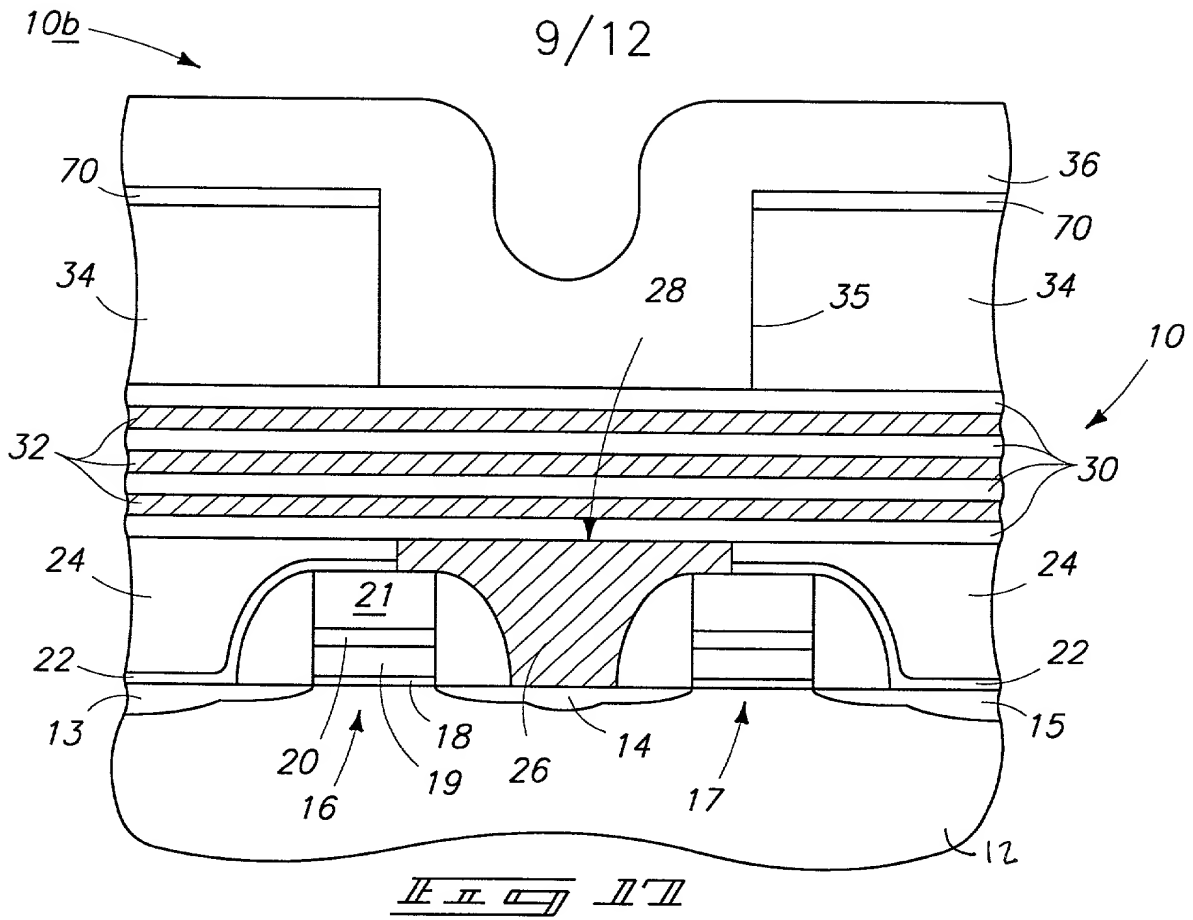


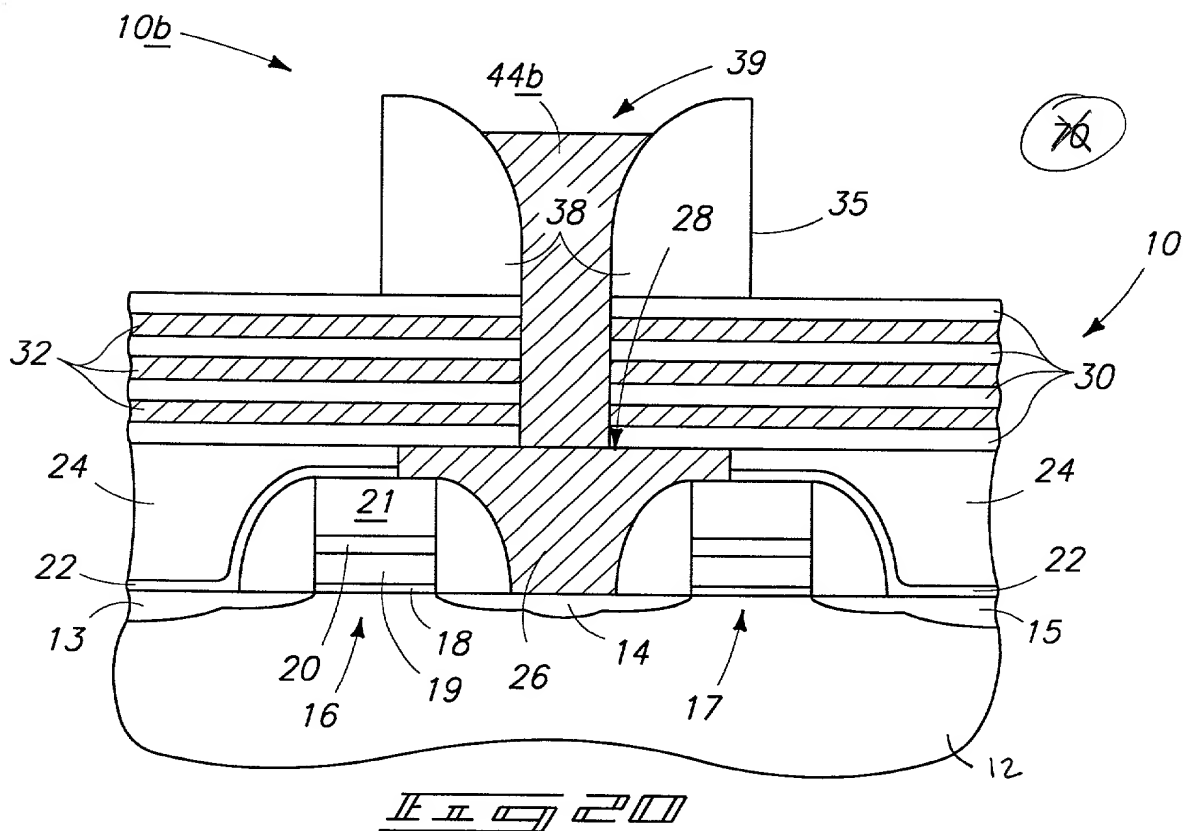
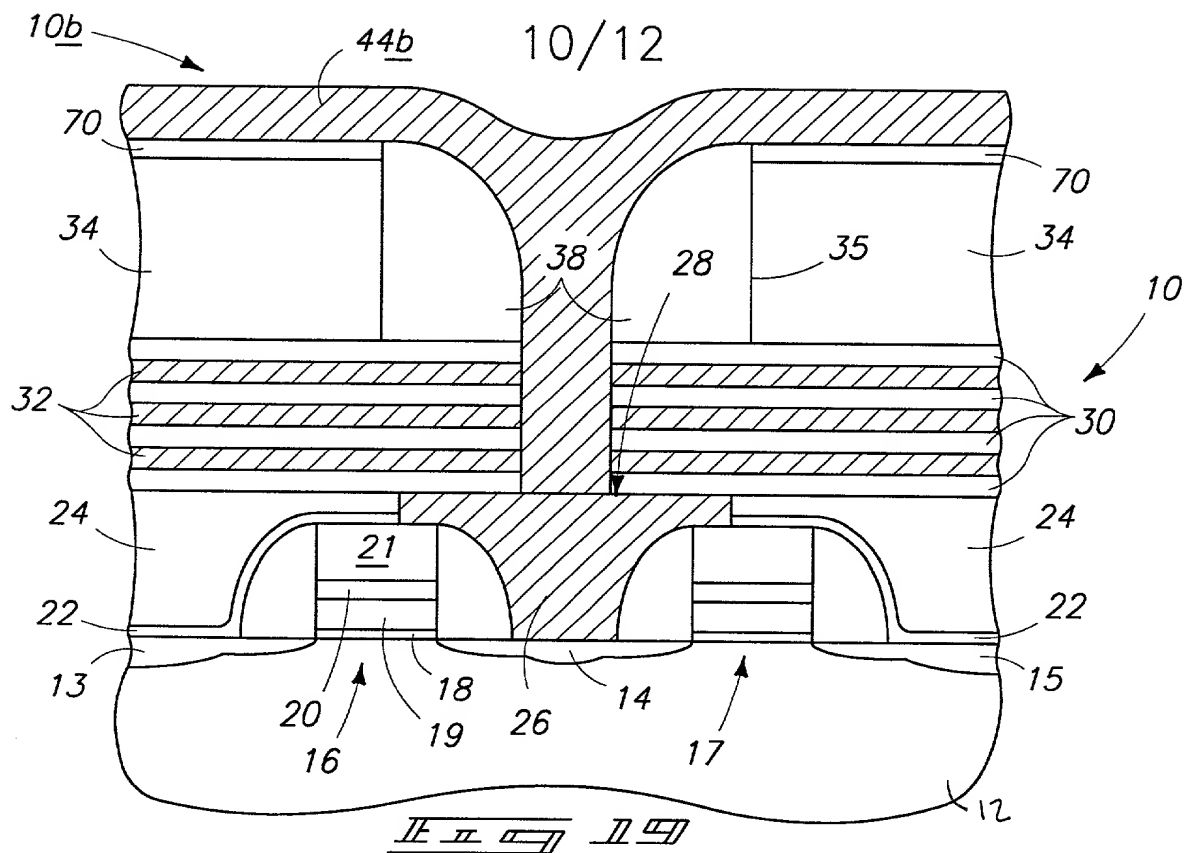
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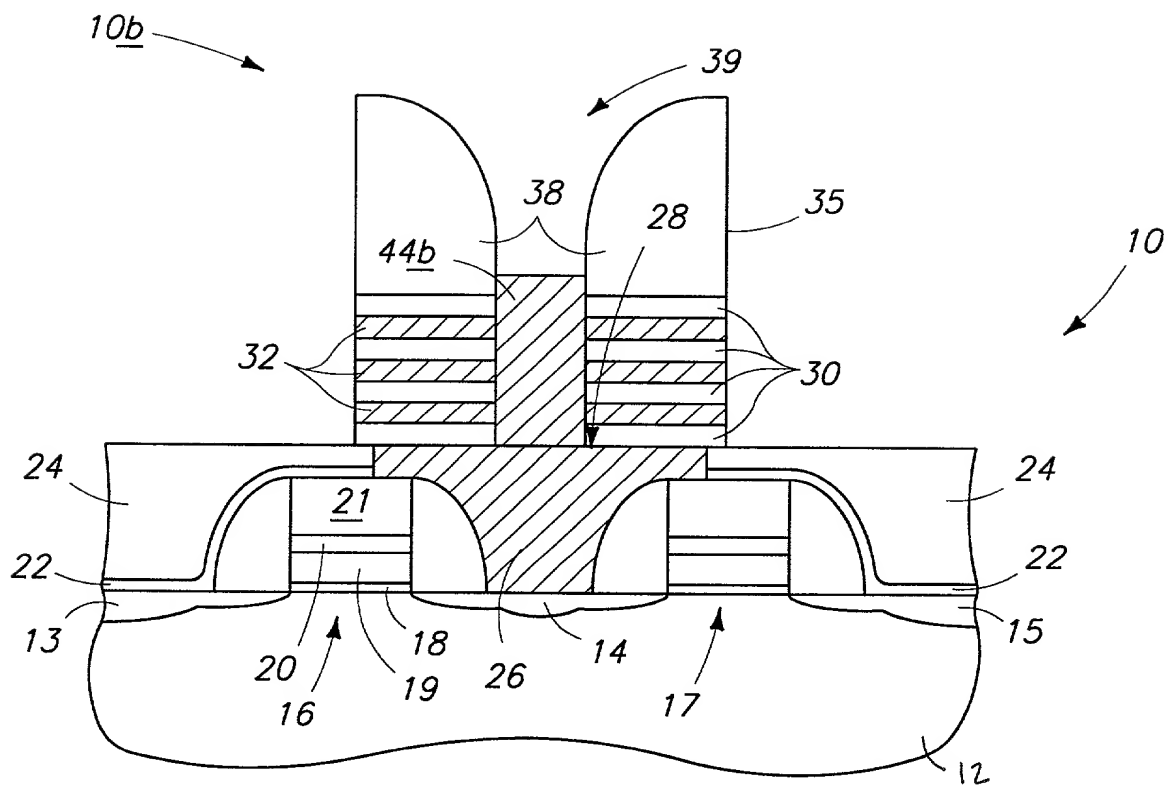


Fig. 11

